Overview

HP EliteDesk 800 G6 Desktop Mini Business PC

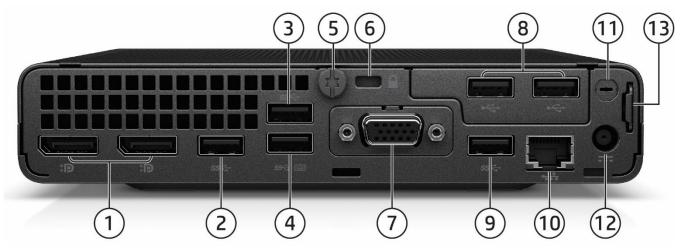


- 1. Type-C[®] SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
- 2. Type-A SuperSpeed USB 10Gbps signaling rate port
- 3. Type-A SuperSpeed USB 5Gbps signaling rate port (charge support up to 5V/2.1A)
- 4. Combo Audio Jack with CTIA and OMTP headset support
- 5. Dual-state power button
- 6. Hard drive activity light



Overview

HP EliteDesk 800 G6 Desktop Mini Business PC



- 1. (2) Dual-Mode DisplayPort[™] 1.4 (DP++)
- 2. Type-A SuperSpeed USB 5Gbps signaling rate port
- 3. Type-A SuperSpeed USB 5Gbps signaling rate port (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS)
- 4. Type-A SuperSpeed USB 10Gbps signaling rate port (Supporting wake from S4/S5 with keyboard/mouse connected and enabled in BIOS) Cover release thumbscrew
- 5. Cover release thumbscrew
- 6. Standard cable lock slot (10 mm)
- 7. (1) Flex Port 1, choice of:
 - HDMI 2.0a Fiber NIC (100Mbps and 1Gbps)
 - VGA 2.0a SerialPort (AMO only)
 - DisplayPort[™] 1.4 Thunderbolt 3 (AMO only)
 - Type-C[™] SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort[™] Alt Mode and 100W Power Intake
 - Intel[®] I225-LM 2.5 Gigabit Network Connection LOM (non-vPro)
 - Dual Type A SuperSpeed USB 10Gbps signaling rate port

Not Shown

Slots	(1) Internal M.2 2230 connector for WLAN
	(2) Internal M.2 SSD storage 2242 and 2280 connector
Bays	(1) 2.5- inch SATA drive Bay (not available on 95W processor)
Mounting	Support for

- VESA Sleeve Standalone
- Quick Release Bracket
- B300/B500 Mounting bracket
- Integrated Work Center Stand

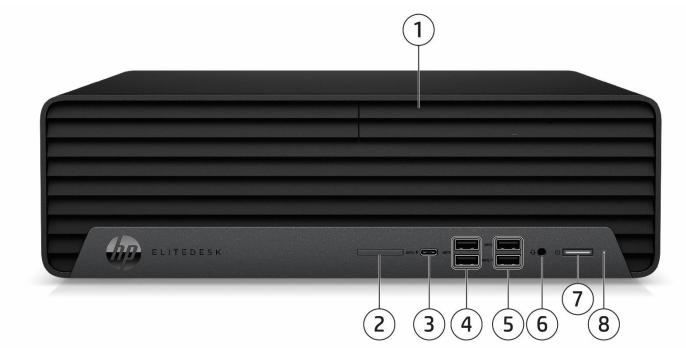
- 8. (1) Flex Port 2, choice of:
 - VR Ready NVIDIA GTX 1660 Ti discrete GPU
 - Dual Type-A Hi-Speed USB 480Mbps signaling rate port
 - SerialS-232
- 9. Type-A SuperSpeed USB 10Gbps signaling rate port
- 10. RJ45 network connector
- 11. External WLAN antenna opening
- 12. Power connector
- 13. Retractable Padlock loop

hp

Not all configuration components are available in all regions/countries. c06648254 – DA 16667 – Worldwide – Version 19 – March 22, 2021

Overview

HP EliteDesk 800 G6 Small Form Factor Business PC



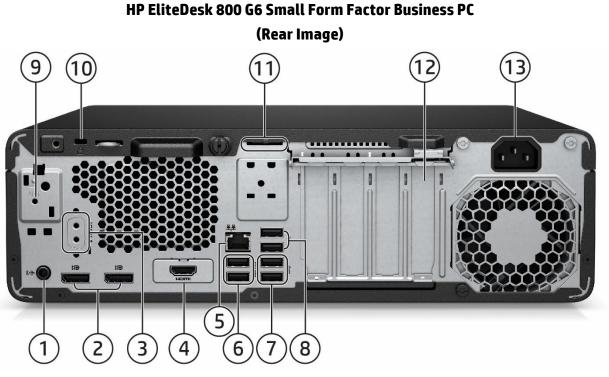
- 1. Optional Slim optical drive
- 2. Optional SD 4 Card Reader
- 3. Type-C[®] SuperSpeed USB 10Gbps signaling rate port (charge support

up to 5V/3A)

- 4. Type A SuperSpeed USB 10Gbps signaling rate port (2)
- 5. Type A SuperSpeed USB 5Gbps signaling rate port (2) (1 with charge support up to 5V/1.5A)

- 6. Combo Audio Jack with CTIA and OMTP headset support
- 7. Dual-state power button
- 8. Hard drive activity light

Overview



- 1. Audio line-out connector
- 2. Dual-Mode DisplayPort[™] 1.4a (DP++) (2)
- 3. Optional Serial port (shown here not installed)
- 4. Optional port, choice of (shown here HDMI installed):
 - DisplayPort[™] Dual Type A SuperSpeed USB
 - HDMI 2.0a 10Gbps signaling rate port
 - VGA
 - USB-C[®] SuperSpeed USB 10Gbps signaling rate port or serial port (USB-C[®] option has alt mode DisplayPort[™] 1.4 and 15W output)
- 5. RJ45 network connector

- 6. Type A Hi-Speed USB 480 Mbps signaling rate port with wake from S4/S5 (2)
- 7. Type A SuperSpeed USB 10Gbps signaling rate port (2)
- 8. Type A SuperSpeed USB 5Gbps signaling rate port (2)
- 9. Optional Internal WLAN antenna cover (shown here not installed)
- 10. Standard cable lock slot
- 11. Optional intrusion sensor/hood lock (shown here not installed)
- 12. Optional Thunderbolt PCIe card with USB-C[®] (shown here not installed)
- 13. Power cord connector

Slots

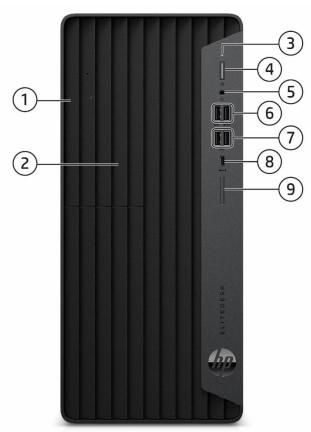
<u>Not shown</u>

- Bays
- (2) PCI Express x16 graphics connectors; one wired as an x4
- (2) PCI Express x1
- (2) internal M.2 SSD storage (2242 and 2280 connector)
- (1) internal M.2 WLAN (2230 connector)

- (1) 2.5" internal storage drive bay(2) 3.5" internal storage drive bay (convertible to 2.5")
- (1) 9.5 mm slim optical drive bay



Overview

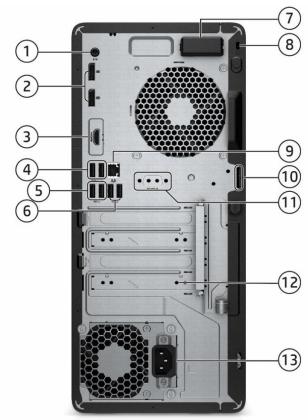


HP EliteDesk 800 G6 Tower Business PC

- 1. Optional Slim optical drive
- 2. External 5.25-inch Half-Height Drive Bay (behind bezel)
- 3. Hard drive activity light
- 4. Dual-state power button
- 5. Combo Audio Jack with CTIA and OMTP headset support
- 6. Type A SuperSpeed USB 5Gbps signaling rate port (charge support up to 5V/1.5A) (2)
- 7. Type-A SuperSpeed USB 10Gbps signaling rate port (2)
- 8. Type-C[®] SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
- 9. Optional SD card 4.0 reader



Overview



HP EliteDesk 800 G6 Tower Business PC

5.5

- 1. Audio line-out jack for powered audio devices
- 2. Dual-Mode DisplayPort[™] 1.4 (DP++) (2)
- 3. Optional port, choice of (shown here HDMI installed):
 - DisplayPort[™] 1.4 Dual Type A SuperSpeed USB
 - HDMI 2.0a 10Gbps signaling rate port
 - VGA
 - USB-C[®] SuperSpeed USB 10Gbps signaling rate port or serial port (USB-C[®] option has alt mode DisplayPort[™] 1.4 and 15W output)
- 4. Type A Hi-Speed USB 480 Mbps signaling rate port with wake from S4/S5 (2)
- 5. Type A SuperSpeed USB 10Gbps signaling rate port (2)

Not shown

Slots

- (2) PCI Express x16 graphics connectors; one wired as an x4(2) PCI Express x1
- (2) internal M.2 SSD storage (2242 and 2280 connector)
- (1) internal M.2 WLAN (2230 connector)

- 6. Type A SuperSpeed USB 5Gbps signaling rate port (2)
- 7. Optional Internal WLAN antenna cover (shown here installed)
- 8. Standard cable lock slot
- 9. RJ-45 (network) jack
- 10. Optional intrusion sensor/hood lock (shown here not installed)
- 11. Optional serial port (shown here not installed)
- 12. Optional Thunderbolt PCIe card with USB-C[®] (shown here not installed)
- 13. Power cord connector

Bays

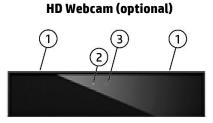
- (1) 2.5" internal storage drive bay
- (2) 3.5" internal storage drive bay (convertible to 2.5")
- (1) 5.25" half-height drive bay
- (1) 9.5mm slim optical drive bay



Overview

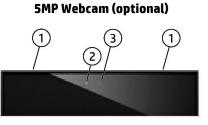


1. Camera (optional)



Dual Microphones
 Webcam Light
 HD Webcam

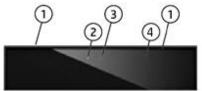
Speakers (optional)



2.

Dual Microphones
 Webcam Light
 SMP Webcam

5MP Webcam with Infrared (IR) Sensors (optional)



Dual Microphones
 Webcam Light
 IR/5MP Webcam
 IR Light

*Available Options: Touch, Non-Touch, HP Sure View (24" Display Only), and Discrete Graphics



Overview

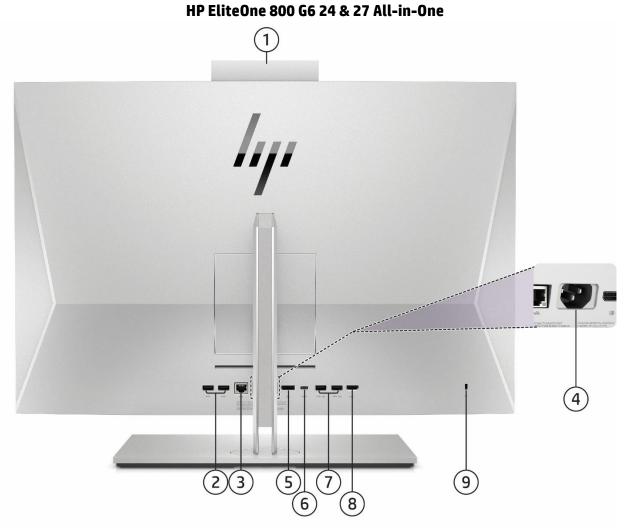
HP EliteOne 800 G6 24 & 27 All-in-One*



- 1. Type-A SuperSpeed USB 10Gbps signaling rate port (charge support up to 5V/3A)
- 2. Type-C[®] SuperSpeed USB 10Gbps signaling rate port (charge support up to (5V/3A)
- 3. Combo Audio Jack with CTIA and OMTP headset Support



Overview



Rear components and rear ports

- 1. Camera (optional)
- 2. Type-A SuperSpeed USB 10Gbps signaling rate port (x2)
- 3. RJ-45 network connector/jack
- 4. Power Connector
- 5. Dual-Mode DisplayPort[™]1.4 (DP++)

- 6. Type-C[®] SuperSpeed USB 10Gbps signaling rate port (charge support up to (5V/3A)
- 7. Type-A SuperSpeed USB 5Gbps signaling rate port (x2)
- 8. HDMI-in 2.0a connector
- 9. Standard cable lock slot



Overview

HP EliteOne 800 G6 24 & 27 All-in-One



- **Dual-State Power button** 1.
- 2. **OSD** control buttons
- 3. SD card reader 4.0 (optional)

Bottom

4.

5.

Not shown Slots (1) internal M.2 PCIe x1 connector for optional wireless NIC

(2) internal M.2 PCIe x4 connector for optional m.2 SSD

VESA

Fingerprint Sensor (optional)

HP Sure View Button (optional on 23.8" only)

Support for VESA 100 mounting system on back of PC chassis (mounting hardware sold separately)



AT A GLANCE

- Choice of four form factors: Tower, Small Form Factor, Desktop Mini and All-In-One
- HP developed and engineered UEFI V2.7 BIOS supporting security, manageability and software image stability
- Intel[®] Q470 chipset supporting Intel[®] 10th generation Core[™] processors, featuring integrated Intel[®] UHD Graphics and Intel[®] vPro[™] Technology (available with Core i3, Core i5, Core i7 and Core i9 processors) ^{1,4}
- Processors up to 65W on AiO
- Processors up to 95W on DM
- Processors up to 125W on DM, TWR and SFF
- Intel[®] Optane[™] Memory H10 with Solid State Storage
- Intel[®] UHD graphics with optional discrete graphics configure systems to up to 7 monitors (TWR, SFF and DM 35W)
- Intel[®] Ethernet Connection I219LM GbE LOM integrated network connection
- Intel[®] Wi-Fi 6 + BT5 (802.11AX 2x2)
- DDR4 Synchronous Dynamic Random Access Memory (SDRAM) (Transfer rates up to 2933 MT/s)²
- Support for up to 7 monitors via two standard DisplayPort[™] 1.4 ports, a configurable Flex i/o port for video options and a discrete graphics card on TWRs, SFFs and DMs. AiO supports up to two additional monitors via DisplayPort[™] or Type-C[®] USB in alternate mode.
- Configurable FlexPort which provides the following choices: HDMI 2.0, Serial, VGA, DisplayPort[™] 1.4, or USB Type-C[™] with DisplayPort[™] 1.4 (USB Type-C[®] with DisplayPort[™] 1.4 with Power Delivery {PD] on DMs), Thunderbolt 3.0 (port on DM, PCIe card on TWR, SFF) and Dual USB Type-A for (TWRs, SFFs and DMs). See Ports section for port availability by platform. FlexPort not supported on AIO.
- 2nd FlexPort available for configuration on the HP EliteDesk G6 Desktop Minis with the following ports: Serial, and Dual USB Type-A. FlexPort not supported on AIO.
- Configurable NVIDA[®] GeForce[®]VR ready discrete graphics card with (3) mini-DisplayPorts and (1) micro-HDMI video port for DM⁵ to support up to (7) monitors with minimum 4K resolution and option to connect up to (3) monitors with 5K resolution via graphics card.
- Configurable AMD[®] Radeon and NVIDA[®] GeForce[®] VR ready discrete graphics on AiO.⁵
- Configurable AMD[®] Radeon, NVIDA[®] GeForce[®] and NVIDA[®] Quadro[®] VR ready discrete graphics on TWR ⁵
- Compatibility with HP Mini-In-One 24 Display (800 G6 DM with 100W USB-C +PD option card)
- Compatible with HP Reverb VR Headset⁸ (AiO, TWR and DM)
- Models can be configured with multiple data drives in a RAID array and support RAID 1 configured from factory.
- Zoom Rooms edition available (AiO, DM) with Win IoT
- Audio by Bang & Olufsen (AiO)
- Intel[®] Unite[™] available (AiO, DM)⁶
- Integrated Low Blue Light Panels on AiO (excludes Sure View and Touch Models)
- Enhanced Security whit HP Security Suite (Refer to Security Section for details)
- ENERGY STAR[®] certified. EPEAT[®] 2019 registered where applicable. EPEAT[®] registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1-2018.⁷
- CCC, CECP and SEPA Certified (TWR/SFF/DM/AiO)
- TCO Edge for AiO (TCO Edge not available for models with HP Sure View)
- TCO (TWR/SFF/DM)
- PC chassis and all internal components and modules are manufactured with low halogen content ³
- Dust filter available for following platforms (35W DM, SFFs and TWRs)
- All form factors undergo up to 13 MIL-STD tests⁹
- Protected by HP Services, including limited warranties up to 3-3-3 (terms and conditions vary by country; certain restrictions and exclusions apply); Care Packs available with up to 5 years Next Business Day Onsite Hardware Support
- Compliance with CE (Class B) / FCC (Class B) / UL (UL60950-1 /UL62368-1) / CSA (CSA C22.2 No.60950-1-07 / CSA C22.2 No. 62368-1-14) / ICES-003 / CCC / VCCI (Class B) / KCC (Class B)
- Fiber NIC (100Mbps and 1Gbps) cards would not be available in some selected European countries and Korea.

1. Multi core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a measurement of higher performance. 2. Maximum transfer rate only available with Intel[®] Core i7 and Core i9 Processors.



Features

3. External power supplies, power cords, cables and peripherals are not low halogen. Service parts obtained after purchase may not be low halogen.

4. Some functionality of vPro technology, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependent on 3rd party software providers. Compatibility of this generation of Intel vPro technology-based hardware with with future "virtual appliances" is yet to be determined.

5. VR-ready as optional feature, requires specific configuration to support.

6. Intel[®] Unite[™] must be configured at the factory.

7. Based on US EPEAT[®] registration according to IEEE 1680.1-2018 EPEAT[®]. Status varies by country. Visit http://www.epeat.net for more information.

8. Availability may vary by country.

9. MIL-STD drop test not performed for All-in-Ones. MIL-STD testing is not intended to demonstrate fitness for U.S. Department of Defense contract requirements or for military use. Test results are not a guarantee of future performance under these test conditions. Accidental damage requires an optional HP Accidental Damage Protection Care Pack.

NOTE: See important legal disclosures for all listed specs in their respective feature's sections

PRODUCT NAME

HP EliteDesk 800 G6 Tower PC HP EliteDesk 800 G6 Small Form Factor PC HP EliteDesk 800 G6 Desktop Mini PC HP EliteOne 800 G6 24 All-in-One PC HP EliteOne 800 G6 27 All-in-One PC

OPERATING SYSTEM

Preinstalled	Windows [®] 10 Pro 64 ¹ Windows [®] 10 Pro 64 (National Academic License) ² Windows [®] 10 Home 64 ¹ Windows [®] 10 Home 64 Single Language ¹
Web-supported only	FreeDOS Windows® 10 Enterprise 641
web-supported only	

1. Not all features are available in all editions or versions of Windows. Systems may require upgraded and/or separately purchased hardware, drivers, software or BIOS update to take full advantage of Windows functionality. Windows 10 is automatically updated, which is always enabled. ISP fees may apply and additional requirements may apply over time for updates. See http://www.windows.com/.

2. Some devices for academic use will automatically be updated to Windows 10 Pro Education with the Windows 10 Anniversary Update. Features vary; see https://aka.ms/ProEducation for Windows 10 Pro Education feature information.

NOTE: Your product does not support Windows 8 or Windows 7. In accordance with Microsoft's support policy, HP does not support the Windows[®] 8 or Windows 7 operating system on products configured with Intel[®] and AMD[®] 7th generation and forward processors or provide any Windows[®] 8 or Windows 7 drivers on http://www.support.hp.com. A full list of HP products and the Windows 10 versions tested is available on the HP support website. https://support.hp.com/us-en/document/c05195282

SUPPORTED VERSIONS

HP tested Windows 10, version 1809 on this platform. For testing information on newer versions of Windows 10, please see https://support.hp.com/document/c05195282

CHIPSET

	<u>DM</u>	<u>SFF</u>	<u>twr</u>	<u>Ai0</u>
Intel [®] Q470 PCH-H− vPro™	<u>X</u>	<u>X</u>	<u>X</u>	<u>X</u>



PROCESSORS

Intel® 10 th Generation Core™ Processors	DM	SFF	TWR	<u>Ai0</u>
Intel® Core™ i9 10900K Processor with Intel® UHD Graphics 630 (3.7GHz, up to 5.3 GHz with Intel® Turbo Boost³, 20MB cache, 10 cores) 125W ^{1,2,4} Supports Intel® vPro™ Technology ⁴	X	x	x	
Intel [®] Core [™] i9 10900 Processor with Intel [®] UHD Graphics 630 (2.8GHz, up to 5.2 GHz with Intel [®] Turbo Boost ³ , 20MB cache, 10 cores) 65W ^{1,2} Supports Intel [®] vPro [™] Technology ⁴	X	x	x	x
Intel® Core™ i9 10900T Processor with Intel® UHD Graphics 630 (1.9GHz, up to 4.6 GHz with Intel® Turbo Boost ³ , 20MB cache, 10cores) 35W ^{1,2} Supports Intel® vPro™ Technology ⁴	X			
Intel® Core™ i7 10700K Processor with Intel® UHD Graphics 630 (3.8 GHz, up to 5.1 GHz with Intel® Turbo Boost ³ , 16MB cache, 8 cores) 125W ^{1,2,4} Supports Intel® vPro™ Technology ⁴	X	x	x	
Intel [®] Core [™] i7 10700 processor with Intel [®] UHD Graphics 630 (2.9 GHz, up to 4.8 GHz with Intel [®] Turbo Boost ³ , 16 MB cache, 8 cores) 65W ^{1,2} Supports Intel [®] vPro [™] Technology ⁴	X	x	x	x
Intel® Core™ i7 10700T Processor with Intel® UHD Graphics 630 (2.0 GHz, up to 4.5 GHz with Intel® Turbo Boost ³ ,16MB cache, 8 cores) 35W ^{1,2} Supports Intel® vPro™ Technology ⁴	x			
Intel [®] Core [™] i5 10600K processor with Intel [®] UHD Graphics 630 (4.1 up to 4.8 GHz with Intel [®] Turbo Boost ³ , 12 MB cache, 6 cores) 125W ^{1, 2,4} Supports Intel [®] vPro [™] Technology ⁴	X	x	x	
Intel [®] Core [™] i5 10600 processor with Intel [®] UHD Graphics 630 (3.3 GHz, 12 MB cache, 6 cores) 65W ^{1, 2} Supports Intel [®] vPro [™] Technology ⁴	x	x	X	x
Intel [®] Core™ i5 10600T processor with Intel [®] UHD Graphics 630 (2.4 GHz 12 MB cache, 6 cores) 35W ^{1, 2} Supports Intel [®] vPro™ Technology ⁴	x			
Intel® Core™ i5 10500 processor with Intel® UHD Graphics 630 (3.1 GHz, 12 MB cache, 6 cores) 65W ^{1, 2} Supports Intel® vPro™ Technology ⁴	X	x	x	x
Intel [®] Core™ i5 10500T processor with Intel [®] UHD Graphics 630 (2.3 GHz, 12 MB cache, 6 cores) 35W ^{1, 2} Supports Intel [®] vPro™ Technology ⁴	X			
Intel® Core™ i5 10400 processor with Intel® UHD Graphics 630 (2.9 GHz, 12 MB cache, 6 cores) 65W ^{1, 2}	X	x	x	x
Intel [®] Core™ i5 10400T processor with Intel [®] UHD Graphics 630 (2.0 GHz, 12 MB cache, 6 cores) 35W ^{1, 2}	x			
Intel [®] Core™ i3 10320 processor with Intel [®] UHD Graphics 630 (3.8 GHz, 8 MB cache, 4 cores) 65W ¹	X	X	x	x
Intel® Core™ i3 10300 processor with Intel® UHD Graphics 630 (3.7 GHz, 8 MB cache, 4 cores) 65W ¹	X	X	X	x



Features

Intel® Core $^{\rm TM}$ i3 10300T processor with Intel® UHD Graphics 630 (3.0 GHz, 8 MB cache, 4 cores) 35W^1	х			
Intel® Core™ i3 10100 processor with Intel® UHD Graphics 630 (3.6 GHz, 6 MB cache, 4 cores) 65W¹	X	X	X	X
Intel® Core™ i3 10100T processor with Intel® UHD Graphics 630 (3.0 GHz, 6 MB cache, 4 cores) 35W¹	х			

1: Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a mea configuration surement of higher performance.

2. Intel[®] Optane[™] memory system acceleration does not replace or increase the DRAM in your system.

3. Intel[®] Turbo Boost technology requires a PC with a processor with Intel Turbo Boost capability. Intel Turbo Boost performance varies depending on hardware, software and overall system. See http://www.intel.com/technology/turboboost for more information.

4. Some functionality of vPro technology, such as Intel Active management technology and Intel Virtualization technology, requires additional 3rd party software in order to run. Availability of future "virtual appliances" applications for Intel vPro technology is dependent on 3rd party software providers. Compatibility with future "virtual appliances" is yet to be determined.

NOTE: Memory speed 2666 and 2933 MT/s can be achieved via two UDIMMs per channel (2DPC) when populated with the same part number.

Intel® Pentium® Processors	DM	<u>SFF</u>	TWR	<u>Ai0</u>
Intel® Pentium® Gold G6600 processor with Intel® UHD Graphics 630 (4.2 GHz, 4 MB cache, 2 cores) 65W ¹	X	X	X	X
Intel® Pentium® Gold G6500 processor with Intel® UHD Graphics 630 (4.1 GHz, 4 MB cache, 2 cores) 65W ¹	X	X	X	X
Intel® Pentium® Gold G6500T processor with Intel® UHD Graphics 630 (3.5GHz, 4 MB cache, 2 cores) 35W ¹	X			
Intel® Pentium® Gold G6400 processor with Intel® UHD Graphics 610 (4.0 GHz, 4 MB cache, 2 cores) 65W ¹	X	X	X	X
Intel® Pentium® Gold G6400T processor with Intel® UHD Graphics 610 (3.4 GHz, 4 MB cache, 2 cores) 35W ¹	X			

1: Multi-core is designed to improve performance of certain software products. Not all customers or software applications will necessarily benefit from use of this technology. Performance and clock frequency will vary depending on application workload and your hardware and software configurations. Intel's numbering, branding and/or naming is not a mea configuration surement of higher performance.



GRAPHICS

Integrated Intel [®] Graphics	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>Ai0</u>
Intel® UHD Graphics 630 (integrated on 10 th gen Core i9/i7/i5/i3, Pentium® Gold G6600, G6500)	X	X	X	x
Intel® UHD Graphics 610 (integrated on 10 th gen Pentium® Gold G6400, Celeron® G5900, G5920)	X	X	X	x
Optional Discrete Graphics Solutions	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>Ai0</u>
NVIDIA [®] GeForce [®] RTX 2080 Super 8GB FH 3DP HDMI Graphics Card*			X	
NVIDIA [®] GeForce [®] RTX 2070 Super 8GB FH 3DP HDMI Graphics Card				X
NVIDIA® GeForce® RTX 2060 Super 8GB FH DP HDMI DVI-D Graphics Card*			X	
NVIDIA [®] Quadro P2200 5GB 4DP Graphics Card			X	
NVIDIA [®] Quadro P1000 4GB 4mDP Graphics Card			X	
NVIDIA [®] Quadro P620 2GB Graphics Card		X	X	
NVIDIA [®] Quadro P400 2GB Graphics Card		X	X	
NVIDIA [®] GeForce [®] GTX 1660Ti 6GB HMDI, DP Graphics Card**	Х			
AMD [®] Radeon™ RX 5300 3GB NGC Graphics Card				X
AMD [®] Radeon™ RX 550X 4GB DP HDMI Graphics Card		X	X	
AMD [®] Radeon™ R7 430 2GB GDDR5 64bit DP+VGA***		Х	X	
AMD [®] Radeon™ R7 430 2GB GDDR5 64bit 2DP		X	X	

*Requires 550W chassis

** Only available on the Desktop Mini with a 35W Processor and supports (3) Mini DP 1.4 Ports and (1) Micro –HDMI 2.0 port in order to drive up to 7 displays directly on the Desktop Mini.

***Not available in all regions

NOTE: The TWR can support a single discrete graphics card up to 300W with a 550W Power Supply.

iters and Cables	DM	<u>SFF</u>	<u>TWR</u>	<u>Ai0</u>
HP DisplayPort™ Cable	X	X	X	X
HP DisplayPort™ to DVI-D Adapter	X	X	X	X
HP DisplayPort™ to HDMI True 4K Adapter	X	X	X	X
HP DisplayPort™ to VGA Adapter	X	X	X	X
HP USB to Serial Port Adapter	X	X	X	X
HP USB-C [®] to HDMI 4K Adapter	X	X	X	X
HP USB-C [®] to DisplayPort Adapter	X	X	X	X
HP DVI Cable	X			X
HP HDMI Standard Cable Kit (HDMI)		X	X	X
HP DVI Cable Kit	X			X
Micro HDMI to HDMI Adapter	X	X	X	
Mini DisplayPort to DisplayPort Adapter	X			



Features

STORAGE

3.5 inch SATA Hard Disk Drives (HDD)	<u>DM</u>	<u>SFF</u>	<u>twr</u>	<u>Ai0</u>
500GB 7200RPM 3.5in SATA HDD		X	X	
1TB 7200RPM 3.5in SATA HDD		X	X	
2TB 7200RPM 3.5in SATA HDD		X	X	
2.5 inch SATA Hard Disk Drives (HDD)	<u>DM</u>	<u>SFF</u>	TWR	<u>Ai0</u>
500GB 7200RPM 2.5in SATA HDD	X	X	X	
1TB 7200RPM 2.5in SATA HDD	X	X	X	
2TB 5400RPM 2.5in SATA HDD	X	X	X	
500GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD*	X	X	X	
500GB 7200RPM 2.5in Self Encrypted Federal Information Processing Standard SATA HDD*	x	x	x	

* Storage DriveLock does not work with Self Encrypting or Optane based storage

M.2 PCIe NMVe Solid State Drives (SSD)

2 PCIe NMVe Solid State Drives (SSD)	<u>DM</u>	<u>SFF</u>	<u>twr</u>	<u>Ai0</u>
256GB M.2 2280 PCIe NVMe SSD	X	X	X	X
512GB M.2 2280 PCIe NVMe SSD	X	Х	X	X
128GB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
256GB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
512GB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
1TB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	X	X	X
2TB M.2 2280 PCIe NVMe Three Layer Cell SSD	X	Х	X	X
256GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD*	X	X	X	X
512GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD*	X	X	X	X
256GB Intel® Optane™ Memory H10 with Solid State Storage*	X	X	X	Х
512GB Intel® Optane™ Memory H10 with Solid State Storage*	X	X	X	X

* Storage DriveLock does not work with Self Encrypting or Optane based storage

tical Disc Drives	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>Ai0</u>
HP 9.5mm Slim DVD-ROM Drive		X	X	
HP 9.5mm Slim DVD Writer Drive		X	X	
HP 9.5mm Slim Blu-Ray Writer Drive		X	X	

Media Card Reader	DM	<u>SFF</u>	<u>TWR</u>	<u>Ai0</u>
SD 4.0 with 5-in-1 Interface (Supports SD, SDXC, SD	IC, UHS-I, UHS-II)	X	X	X

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.



MEMORY

Memory Type	DM	<u>SFF</u>	<u>TWR</u>	<u>Ai0</u>
DDR4-2933 (Transfer rates up to 2933 MT/s), 64 GB, 2 SODIMM ¹	X			X
DDR4-2666 (Transfer rates up to 2666 MT/s), 64 GB, 2 SODIMM	X			X
DDR4-2933 (Transfer rates up to 2933 MT/s), 128 GB, 4 DIMM ¹		X	X	
DDR4-2666 (Transfer rates up to 2666 MT/s), 128 GB, 4 DIMM		X	X	

emory Configuration	DM	<u>SFF</u>	TWR	<u>Ai0</u>
4 GB (1 x 4 GB)	X	X	X	X
8 GB (2 x 4 GB)	X	X	X	X
8 GB (1 x 8 GB)	X	X	X	X
16 GB (2 x 8 GB)	X	X	X	X
16 GB (1 x 16 GB)	X	X	X	X
32 GB (2 x 16 GB)	X	X	X	X
32 GB (4 x 8 GB)		X	X	
32 GB (1 x 32 GB)	X	X	X	X
64 GB (4 x 16 GB)		X	X	
64 GB (2 x 32 GB)	X	X	X	X
128 GB (4 x 32 GB)		X	X	

1. Only available with Intel Core i7 and Core i9 processors.

NOTE: For systems configured with more than 3 GB of memory and a 32-bit operating system, all memory may not be available due to system resource requirements. Addressing memory above 4 GB requires a 64-bit operating system.

Memory modules support data transfer rates up to 2666 MT/s or 2933 MT/s as depending on processor config; with 1 DIMM per channel. Additional DIMM loading on any channel may impact maximum memory speed. Actual data rate is determined by the system's configured ; See processor specifications for supported memory data rate.

NOTE: All memory slots are customer accessible / upgradeable.

NETWORKING/COMMUNICATIONS

Ethernet (RJ-45)	<u>DM</u>	<u>SFF</u>	TWR	<u>AiO</u>
Intel [®] I225LM 2.5 Gigabit Network Connection LOM (optional)	X			
Intel® Ethernet I210-T1 PCIe x1 Gb Network Interface Card (optional)		X	Х	
Intel [®] I219-LM Gigabit Network Connection LOM (standard)	X	X	X	X

Wireless ¹	DM	<u>SFF</u>	TWR	<u>Ai0</u>
Intel® Wi-Fi 6 AX201 + BT5 (802.11AX 2x2 vPro, supporting gigabit file transfer speed)	x	x	x	X
Intel® Wi-Fi 6 AX201 + BT5 (802.11AX 2x2 non-vPro, supporting gigabit file transfer speed)	x	x	x	X
Realtek RTL8822CE 802.11ac 2x2 Wi-Fi [®] + BT5	X	X	X	X

1. Wireless access point and Internet service required and not included. Availability of public wireless access points limited. The specifications for the 802.11ax WLAN are draft specifications and are not final. If the final specifications differ from the draft specifications, it may affect the ability of the PC to communicate with 802.11ax WLAN devices. Wi-Fi 6 requires a wireless router, sold separately, that supports 802.11ax (Wi-Fi 6). Only available in countries where 802.11ax is supported.



CEE

TWD

A:0

пΜ

Features

KEYBOARDS AND POINTING DEVICES

Keyboards

Keyboards	DM	<u>SFF</u>	<u>TWR</u>	<u>Ai0</u>
HP Wired Desktop 320K Keyboard	X	X	X	X
HP USB Premium Keyboard	X	X	X	X
HP USB and PS/2 Washable Keyboard ¹	X	X	X	X
HP USB Business Slim Smart Card (CCID) Keyboard	X	X	X	X
HP USB Keyboard	X	X	X	X
HP PS/2 Business Slim Keyboard ¹		X	X	
HP Wireless Business Slim Keyboard and Mouse	X	X	X	X
HP USB Business Slim Antimicrobial Keyboard ²	X	X	X	X
HP Wireless Premium Keyboard and Mouse	X	X	X	X
HP USB Keyboard and Mouse Healthcare Edition	X	X	X	X
Mouse	DM	<u>SFF</u>	TWR	<u>Ai0</u>
HP Wired Desktop 320M Mouse	X	X	X	X
HP PS/2 Mouse ¹		X	X	
HP USB Optical Mouse	X	X	X	X
HP USB Premium Mouse	X	X	X	X
HP USB 1000dpi Laser Mouse	X	X	X	X
HP USB and PS/2 Washable Mouse ¹	X	X	X	
Antimicrobial USB Mouse ²	X	X	X	X
HP USB Hardened Mouse ²	X	X	X	X
HP USB Fingerprint Reader Mouse	X	X	X	X

1. PS/2 port not available on EliteOne 800 G6 AiOs and not available on any EliteDesk 800 G6 DMs

2. Not available in all regions



Features

SECURITY

	DM	<u>SFF</u>	TWR	<u>Ai0</u>
TPM 2.0 (FW: 7.85) endpoint security controller (Infineon SLB9670) shipped with Windows 10. Common Criteria EAL4+ Certified. FIPS 140-2 Level 2 Certified.	х	x	x	x
Solenoid Lock & Intrusion Sensor		X	X	
Intrusion Sensor for DM/AiO (integrated in the PCA, can be enabled/disabled through BIOS)	X			x
Support for chassis cable lock devices	X (10 mm or smaller)	x	x	x
Support for chassis padlocks devices	X	X	X	
HP Fingerprint Sensor (standard on 800 G6 AiO touch models and optional on non-touch models)				x
SATA port disablement (via BIOS)	X	Х	X	
Serial, USB enable/disable (via BIOS)	X	X	X	X
Intel [®] Identify Protection Technology (IPT) ¹	X	X	X	X
Serial, parallel, USB enable/disable (via BIOS)	X	X	X	X
Optional USB Port Disable at factory (user configurable via BIOS)	X	X	X	X
Removable media write/boot control	X	X	Х	X
Power-on password (via BIOS)	X	X	X	X
Setup password (via BIOS)	X	X	Х	X

1. Models configured with Intel[®] Core[™] processors have the ability to utilize advanced security protection for online transactions. IPT, used in conjunction with participating web sites, provides double identity authentication by adding a hardware component in addition to the usual user name and password. IPT is initialized through an HP Client Security module.

PORTS

I/O Ports – Internal Ports	DM	<u>SFF</u>	TWR	<u>Ai0</u>
Internal SATA storage connector(s)	N/A	3	4	N/A
Internal SATA storage connector (Data and Power)	1	N/A	N/A	N/A

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

Standard User Accessible Ports	DM	<u>SFF</u>	<u>TWR</u>	AiO
Type-A Hi-Speed USB		2 (rear)	2 (rear)	
Type-A SuperSpeed USB 5 Gbps signaling rate port	1 (front) 2 (rear)	2 front (1 fast charging), 2 rear	2 front (1 fast charging), 2 rear	2 rear
Type-A SuperSpeed USB 10 Gbps signaling rate port	1 (front) 2 (rear)	2 front; 2 rear	2 front; 2 rear	2 rear 1 side
Type-C [®] SuperSpeed USB 10 signaling rate Gbps port	1 (front)	1 (front)	1 (front)	1 rear 1 side



Features

Video	2 DisplayPort™ 1.4 (rear)	2 DisplayPort™ 1.4 (rear)	1 DisplayPort™ 1.4 (rear)	For models with integrated graphics: 1 DisplayPort [™] 1.4 (rear) 1 USB Type-C [®] with alt mode display or 15W output) (rear) 1 HDMI-In (rear) For models with discrete graphics: 1 DisplayPort [™] 1.4 (rear) 1 USB Type-C [®] with alt mode display or 15W output) (rear) 1 HDMI-In (rear)
Audio	1 Combo Audio Jack with CTIA and OMTP headset support (front)	1 Universal Audio Jack with CTIA headset support (front)); 1 Audio-out (rear),	1 Universal Audio Jack with CTIA headset support (front)); 1 Audio-out (rear),	1 CTIA/OMTP UAJ (side)
Network Interface	1 RJ45 (rear)	1 RJ45 (rear)	1 RJ45 (rear)	1 RJ45 (rear)

(1) Flexible Port 1, choice of <u>one</u> of <u>DM</u><u>SFF</u><u>TWR</u><u>AiO</u>

ollowing				
Type-A SuperSpeed USB 5 Gbps signaling rate port	2 (rear)	2 (rear)	2 (rear)	N/A
Type-C® SuperSpeed USB 10Gbps signaling rate port	1 SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode and power intake via USB Type-C [®] Power Delivery up to 100W (rear)	1 SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode (rear)	1 SuperSpeed USB 10Gbps signaling rate port w/ DisplayPort™ Alt Mode (rear)*	N/A
Thunderbolt™ 3	1 (rear)	1 (rear)	1 (rear)	N/A
Video		1 DisplayPort™ 1.4 <u>or</u> HDMI 2.0 <u>or</u> VGA (rear)	1 DisplayPort™ 1.4 <u>or</u> HDMI 2.0 <u>or</u> VGA (rear)	N/A
Serial (RS-232)	N/A	1 (rear)	1 (rear)	N/A
Fiber NIC Adapter	(1) 100Mbps NIC (rear) (1) 1 Gbps NIC (rear)			N/A
RJ-45 Ethernet NIC	(1) 2.5GbE(rear)			N/A

(1) Flexible Port 2, choice of <u>one</u> of the following:	DM	<u>SFF</u>	<u>MT</u>	<u>Ai0</u>
Type-A USB	2 Hi-Speed USB (rear)			N/A
Serial (RS-232)	1 (rear)			N/A
Discrete Graphics	1 (rear)			N/A

Not all configuration components are available in all regions/countries. c06648254 – DA 16667 – Worldwide – Version 19 – March 22, 2021

NOTE: For Desktop Mini with M.2 Storage config, there will be no SATA drive bracket. If you plan to use or upgrade the storage with any 2.5" SATA drive, please select a DM SATA Drive Bracket (available as both factory configured and after market option).

Slots	DM	<u>SFF</u>	<u>TWR</u>	<u>Ai0</u>
M.2 PCIe	(1) M.2 PCle x1	(1) M.2 PCle x1	(1) M.2 PCIe x1	(1) M.2 PCIe x1
	2230 (for WLAN)	2230 (for WLAN)	2230 (for WLAN)	2230 (for WLAN)
	(2) M.2 PCIe x4	(2) M.2 PCIe x4	(2) M.2 PCle x4	(2) M.2 PCle x4
	2280/2230 Combo	2280/2230 Combo	2280/2230 Combo	2280 Combo (for
	(for storage)	(for storage)	(for storage)	storage)
PCI Express v3.0 x1	N/A	2	2	N/A
PCI Express v3.0 x16 (wired as x4)	N/A	1	1	N/A
PCI Express v3.0 x16	N/A	1 (up to 75W)	1 (up to 300W)	N/A

Bays	DM	<u>SFF</u>	<u>TWR</u>	<u>Ai0</u>
5.25" Half Height (External)	N/A	N/A	1	N/A
9mm Slim Optical Disc Drive (ODD)	N/A	1	1	N/A
SD Card Reader	N/A	1	1	1
2.5" Internal Storage Drive	1	1	1	N/A
3.5" Internal Storage Drive	N/A	2	2	N/A

SATA 2.5" internal storage drive cannot be selected if 2nd M.2, discrete graphic card, or 95W processor is selected.



USB SPECIFICATION AND MARKETING NAME MAPPING TABLE

Marketing Name	Technical Terminology
Hi-Speed USB 480Mbps signaling rate	USB 2.0
SuperSpeed USB 5Gbps signaling rate	USB 3.2 Gen 1
SuperSpeed USB 10Gbps signaling rate	USB 3.2 Gen 2
SuperSpeed USB 20Gbps signaling rate	USB 3.2 Gen 2x2



SOFTWARE COMPONENTS AND APPLICATIONS WITH WINDOWS

BIOS

HP BIOSphere Gen6¹⁶ HP DriveLock & Automatic DriveLock²⁰ BIOS Update via Network HP Secure Erase¹⁸ Absolute Persistence Module¹⁹ Pre-boot Authentication HP Wake on WLAN

Software

HP Desktop Support Utility HP JumpStart HP Privacy Settings HP Setup Integrated OOBE HP Support Assistant ²¹ HP Noise Cancellation Software Buy Office (sold separately)

Manageability Features

HP Driver Packs ²² HP System Software Manager (SSM) (download) HP BIOS Config Utility (BCU) (download) HP Client Catalog (download) HP Image Assistant Gen (download) HP Manageability Integration Kit for Microsoft System Center Configuration Management Gen4 ²³ Ivanti Management Suite (download)²⁴ HP Cloud Recovery³⁹ HP Client Management Script Library (download)

Client Security Software

HP Client Security Suite Gen6²⁵ HP Power On Authentication Windows Defender²⁷

Security Management

Trusted Platform Module TPM 2.0 Embedded Security Chip shipped with Windows 10. (Common Criteria EAL4+ Certified). SATA 0,1 port disablement (via BIOS) Serial, USB enable/disable (via BIOS) Power-on password (via BIOS) Setup password (via BIOS) Support for chassis padlocks and cable lock devices HP Sure Sense³⁴ HP Sure Click³⁸ HP Sure Start Gen6³⁰ HP Sure Run Gen3³⁵ HP Sure Recover Gen3³⁶

16. HP BIOSphere Gen6 is available on select HP Pro and Elite PCs. See product specifications for details. Features may vary depending on the platform and configurations.

18. HP Secure Erase for the methods outlined in the National Institute of Standards and Technology Special Publication 800-88 "Clear" sanitation method. HP Secure Erase does not support platforms with Intel[®] Optane[™].

19. Absolute agent is shipped turned off, and will be activated when customers activate a purchased subscription. Subscriptions can be purchased for terms ranging multiple years. Service is limited, check with Absolute for availability outside the U.S. The Absolute Recovery Guarantee is a limited warranty. Certain conditions apply. For full details visit: http://www.absolute.com/company/legal/agreements/computrace-agreement. Data Delete is an optional service provided by Absolute Software. If utilized, the Recovery Guarantee is null and void. In order to use the Data



Features

Delete service, customers must first sign a Pre-Authorization Agreement and either obtain a PIN or purchase one or more RSA SecurID tokens from Absolute Software.

20. Storage Drivelock does not work with Self Encrypting or Optane based storage.

21. HP Support Assistant requires Windows and Internet access.

22. HP Driver Packs not preinstalled, however available for download at http://www.hp.com/go/clientmanagement.

23. HP Manageability Integration Kit can be downloaded from http://www8.hp.com/us/en/ads/clientmanagement/overview.html. 24. Ivanti Management Suite subscription required.

25. HP Client Security Manager Gen6 requires Windows and is available on select HP Pro and Elite PCs.

27. Windows Defender Opt in Windows 10 and internet connection required for updates.

30. HP Sure Start Gen6 is available on select HP PCs with Intel processors.

34. HP Sure Sense requires Windows 10.

35. HP Sure Run Gen3 is available on select Windows 10 based HP Pro, Elite and Workstation PCs with select Intel® or AMD processors. 36. HP Sure Recover Gen3 is available on select HP PCs and requires an open network connection. Not available on platforms with multiple internal storage drives. You must back up important files, data, photos, videos, etc. before using HP Sure Recover to avoid loss of data. 38. HP Sure Click is available on most HP PCs and supports Microsoft® Internet Explorer, Google Chrome, and Chromium™. Supported attachments include Microsoft Office (Word, Excel, PowerPoint) and PDF files in read only mode, when Microsoft Office or Adobe Acrobat are installed.

39. HP Cloud Recovery is available for HP Elite and Pro desktops and laptops PCs with Intel[®] or AMD processors and requires an open, wired network connection. Note: You must back up important files, data, photos, videos, etc. before use to avoid loss of data. Detail please refer to: https://support.hp.com/us-en/document/c05115630.



ENVIRONMENTAL & INDUSTRY

ENERGY STAR® certified models available

ENERGY STAR[®] certified. EPEAT[®] 2019 registered where applicable. EPEAT [®] registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1-2018.

Low halogen (chassis, all internal components and modules)¹ TAA compliant models available

1. External power supplies, power cords, cables and peripherals are not Low Halogen. Service parts obtained after purchase may not be Low Halogen.

UNIT ENVIRONMENT AND OPERATING CONDITIONS

General Unit Operating Guidelines

- Keep the computer away from excessive moisture, direct moisture and the extremes of heat and cold, to ensure that unit is operated within the specified operating range.
- Leave a 10.2 cm (4 in) clearance on all vented sides of the computer to permit the required airflow.
- Never restrict airflow into the computer by blocking any vents or air intakes.
- Do not stack computers on top of each other or place computers so near each other that they are subject to each other's re-circulated or preheated air.
- Occasionally clean the air vents on the front, back, and any other vented side of the computer. Lint, dust and other foreign
 matter can block the vents and limit the airflow.
- If the computer is to be operated within a separate enclosure, intake and exhaust ventilation must be provided on the enclosure, and the same operating guidelines listed above will still apply.

Temperature Range	Operating: 50° to 95° F (10° to 35° C)¹ Non-operating: -22° to 149° F (-30° to 65° C)
Relative Humidity	Operating: 10% to 90% (non-condensing at ambient) Non-operating: 5% to 95% (non-condensing at ambient)
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50000ft (15240 m)

1. Operating temperature is de-rated 1.0 deg C per 300 m (1000 ft) to 3000 m (10,000 ft) above sea level, no direct sustained sunlight. Maximum rate of change is 10 deg C/Hr. The upper limit may be limited by the type and number of options installed.



HP EliteDesk 800 Desktop Mini G6 series

HP EliteDesk 800 Desktop Eco-Label Certifications & declarations	 This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR[®] ENERGY STAR[®] certified. EPEAT[®] 2019 registered where applicable. EPEAT[®] registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1- 			
System Configuration	2018.	ergy Consumption and Declared No		
Jotem com gu ation	Desktop model is based on a "Typ			
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 50Hz	
Normal Operation (Short idle)	8.9320 W	8.9410 W	8.9190 W	
Normal Operation (Long idle)	6.3380 W	6.3460 W	6.3280 W	
Sleep	1.0520 W	1.1020 W	1.0320 W	
Off	0.8210 W	0.8220 W	0.8200 W	
Heat Dissipation*	Environmental Protection Agency (EP not offer ENERGY STAR® certified con	e ENERGY STAR [®] Logo are compliant w A) ENERGY STAR [®] specifications for co figurations, then energy efficiency dat efficiency power supply, and a Microso 230VAC, 50Hz	mputers. If a model family does a listed is for a typically configured	
Normal Operation (Short idle)	30.4581 BTU/hr	30.4888 BTU/hr	30.4138 BTU/hr	
Normal Operation (Long idle)	21.6126 BTU/hr	21.6399 BTU/hr	21.5785 BTU/hr	
Sleep	3.5873 BTU/hr	3.7578 BTU/hr	3.5191 BTU/hr	
Off	2.7996 BTU/hr	2.8030 BTU/hr	2.7962 BTU/hr	
	NOTE: Heat dissipation is calculated bone hour.	based on the measured watts, assumir	g the service level is attained for	
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound PowerSound Pressure(LwAd, bels)(LpAm, decibels)			
Typically Configured – Idle	2.8 18.8			
Fixed Disk – Random writes	2.8		18.8	
Longevity and Upgrading	This product can be upgraded, pos features and/or components cont	ssibly extending its useful life by s ained in the product may include:	everal years. Upgradeable	
	Spare parts are available through production.	out the warranty period and or for	up to "5" years after the end of	
Batteries	This battery(s) in this product con	nply with EU Directive 2006/66/EC		
	Batteries used in the product do not contain: Mercury greater the1ppm by weight			
	Cadmium greater than 20ppm by weight			
	Battery size: CR2032 (coin cell) Battery type: Lithium			



Features			
Additional Information	2011/65/EC • This HP pro Directive – 2 • This produ Water and T • ENERGY ST country. See 2018. • Plastics pa • This produ ITE-derived • This produ	oduct is designed to comply with the Waste Electrical and E	Electronic Equipment (WEEE) California; Safe Drinking PEAT ® registration varies by According to IEEE 1680.1- d per ISO11469 and ISO1043. Istic (by wt.); Including 10% of life.
Packaging Materials	External:	PAPER/Corrugated	405 g
rackaying materials	Externat:		
	Internal:		
Material Usage	to the HP Ge http://www. • Asbestos • Certain Azo • Certain Bro • Cadmium • Chlorinated • Chlorinated • Chlorinated • Formaldeh • Halogenato • Lead carbo • Lead and L • Mercuric O • Nickel – fin carried by th • Ozone Dep • Polybromin • Polybromin • Polybromin • Polychlorir • Polychlorir	 Certain Azo Colorants Certain Brominated Flame Retardants – may not be used as flame retardants in plastics 	



Features

Packaging Usage	This product does not contain any of the following substances in excess of regulatory limits (refer to the HP General Specification for the Environment at
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf):
	• Asbestos
	Certain Azo Colorants
	Certain Brominated Flame Retardants – may not be used as flame retardants in plastics
	• Cadmium
	Chlorinated Hydrocarbons
	Chlorinated Paraffins
	• Formaldehyde
	Halogenated Diphenyl Methanes
	Lead carbonates and sulfates
	Lead and Lead compounds
	Mercuric Oxide Batteries
	• Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user.
	Ozone Depleting Substances
	Polybrominated Biphenyls (PBBs)
	Polybrominated Biphenyl Ethers (PBBEs)
	Polybrominated Biphenyl Oxides (PBBOs)
	Polychlorinated Biphenyl (PCB)
	Polychlorinated Terphenyls (PCT)
	• Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications.
	Radioactive Substances
	Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible
	manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly
	instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM
	customers who integrate and re-sell HP equipment. Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K _Certificate.pdf
	and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
	Tricp.//www.np.com/npinto/globalchizensnip/envitonment/put/cett.put



HP EliteDesk 800 Small Form Factor G6 series

Eco-Label Certifications & declarations	This product has received or is in the labeled with one or more of these IT ECO declaration • US ENERGY STAR® • ENERGY STAR® certified. EPEAT® country. See http://www.epeat.net 2018.	se marks: 2019 registered wł	nere applicable. E	EPEAT ® registration varies by
System Configuration	The configuration used for the Ene Desktop model is based on a "Typic			e Emissions data for the
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC,	50Hz	100VAC, 50Hz
Normal Operation (Short idle)	12.479 watt	12.579	watt	12.291 watt
Normal Operation (Long idle)	11.193 watt	11.306	watt	11.151 watt
Sleep	0.675 watt	0.7		0.665 watt
Off	0.479 watt	0.5		0.475 watt
Heat Dissipation*	Environmental Protection Agency (EPA not offer ENERGY STAR® compliant cor configured PC featuring a hard disk driv system. 115VAC, 60Hz	figurations, then ene	ergy efficiency data power supply, and a	a listed is for a typically
Normal Operation (Short	42.55339 BTU/hr			41.91231 BTU/hr
idle) Normal Operation (Long idle)			38.02491 BTU/hr	
Sleep	2.30175 BTU/hr	2.40064 E	RTII/hr	2.26765 BTU/hr
Off	1.63339 BTU/hr	1.70841 E		1.61975 BTU/hr
	NOTE: Heat dissipation is calculated ba one hour.			
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	Sound PowerSound Pressure(LwAd, bels)(LpAm, decibels)			
Typically Configured – Idle	3.11 20.7			20.7
Fixed Disk–Random writes	3.41			22.1
Longevity and Upgrading	This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.			
Batteries	This battery(s) in this product comp Batteries used in the product do no Mercury greater the1ppm by weigh Cadmium greater than 20ppm by w Battery size: CR2032 (coin cell)	ot contain: ht	e 2006/66/EC	



Features

	Battery type	: Lithium	
Additional Information	• This produce 2011/65/EC.	ct is in compliance with the Restrictions of Hazardous Subs	stances (RoHS) directive -
	• This HP product is designed to comply with the Waste Electrical and Electronic Equipment (WEEE) Directive – 2002/96/EC.		
		ct is in compliance with California Proposition 65 (State of	California; Safe Drinking
		oxic Enforcement Act of 1986).	
		AR [®] certified. EPEAT [®] 2019 registered where applicable. E www.epeat.net for registration status by country. Accord	
		rts weighing over 25 grams used in the product are marked	
		ct contains a minimum of 35% post-consumer recycled pla	
		post-consumer recycled plastic*	
	• This produ	ct is 95.1% recycle-able when properly disposed of at end	of life.
	*NOTE: Recyc	led plastic content percentage is based on the definition set in th	e IEEE 1680.1-2018 standard.
Packaging Materials	External:	PAPER/Corrugated	1158 g
	Internal:	PLASTIC/EPE (Expanded Polyethylene)	320 g
		PLASTIC/Polyethylene low density	28 g
Material Usage		does not contain any of the following substances in exces neral Specification for the Environment at	s of regulatory limits (refer
		hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pc	lf):
	 Asbestos 		
	Certain Azc		
		minated Flame Retardants – may not be used as flame ret	ardants in plastics
	Cadmium	d I ludva an uka wa	
		d Hydrocarbons	
	 Chlorinated Paraffins Formaldehyde Halogenated Diphenyl Methanes Lead carbonates and sulfates Lead and Lead compounds Mercuric Oxide Batteries Nickel – finishes must not be used on the external surface designed to be frequently handled or 		
	carried by th		
		leting Substances	
		nated Biphenyls (PBBs) nated Biphenyl Ethers (PBBEs)	
	-	nated Biphenyl Oxides (PBBOs)	
		lated Biphenyl (PCB)	
		lated Terphenyls (PCT)	
		hloride (PVC) – except for wires and cables, and certain ret	ail packaging has been
	voluntarily r	emoved from most applications.	
		e Substances	
		ı (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)	
Packaging Usage	HP follows t	hese guidelines to decrease the environmental impact of p	roduct packaging:
	• Eliminate t materials.	he use of heavy metals such as lead, chromium, mercury a	ind cadmium in packaging
	• Eliminate t	he use of ozone-depleting substances (ODS) in packaging	materials.
		kaging materials for ease of disassembly.	
		he use of post-consumer recycled content materials in pac	ckaging materials.
		recyclable packaging materials such as paper and corruga	
	-	e and weight of packages to improve transportation fuel e	
		kaging materials are marked according to ISO 11469 and [
		Ruging matchats are marked according to 150 11405 and L	



Features

End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html
	Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K _Certificate.pdf
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

HP EliteDesk 800 Tower G6 series

Eco-Label Certifications & declarations	 be labeled with one or more of th IT ECO declaration US ENERGY STAR[®] ENERGY STAR[®] certified. EPEAT 	the process of being certified to th lese marks: © 2019 registered where applicable et for registration status by counti	e. EPEAT [®] registration varies by
System Configuration	The configuration used for the Er Desktop model is based on a Typ	ergy Consumption and Declared N ically Configured Desktop.	oise Emissions data for the
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	11.67 W	11.24 W	11.53 W
Normal Operation (Long idle)	9.83 W	10.55 W	9.69 W
Sleep	0.84 W	0.81 W	0.86 W
Off	0.57 W	0.53 W	0.57 W
	family. HP computers marked with th Environmental Protection Agency (Ef not offer ENERGY STAR® compliant c configured PC featuring a hard disk d system.	s for an ENERGY STAR® compliant prod te ENERGY STAR® Logo are compliant to PA) ENERGY STAR® specifications for co onfigurations, then energy efficiency c Irive, a high efficiency power supply, an	with the applicable U.S. omputers. If a model family does lata listed is for a typically nd a Microsoft Windows® operating
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	39.91 BTU/hr	38.44 BTU/hr	39.43 BTU/hr
Normal Operation (Long idle)	33.62 BTU/hr	36.08 BTU/hr	33.14 BTU/hr
Sleep	2.87 BTU/hr	2.77 BTU/hr	2.94 BTU/hr
Off	1.95 BTU/hr	1.81 BTU/hr	1.95 BTU/hr



Features

	NOTE: Heat do one hour.	lissipation is calculated based on the n	neasured watts, assuming t	he service level is attained for
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)		Sound Power (L _{wad} , bels)		ound Pressure .pAm, decibels)
Typically Configured – Idle		3.3		21
Fixed Disk–Random writes		3.3		22
Longevity and Upgrading	features an Spare parts	t can be upgraded, possibly extend d/or components contained in the are available throughout the warr	product may include:	
Batteries	production.		Directive 2006/66/EC	
	This battery(s) in this product comply with EU Directive 2006/66/EC Batteries used in the product do not contain: Mercury greater the1ppm by weight Cadmium greater than 20ppm by weight Battery size: CR2032 (coin cell)			
	Directive – 2 • This produ Water and T • ENERGY S country. Sec • Plastics pa • This produ ITE-derived • This produ	oduct is designed to comply with t 2002/96/EC. Ict is in compliance with California Toxic Enforcement Act of 1986). TAR® certified. EPEAT® 2019 regist e www.epeat.net for registration s arts weighing over 25 grams used i Ict contains a minimum of 35% pos post-consumer recycled plastic* Ict is 95.1% recycle-able when pro	Proposition 65 (State of (ered where applicable. E tatus by country. Accordi n the product are marked st-consumer recycled pla perly disposed of at end (California; Safe Drinking PEAT® registration varies by ng to IEEE 1680.1-2018. d per ISO11469 and ISO1043. stic (by wt.); Including 10% of life.
Packaging Materials	External:	PAPER/Corrugated		1114 g
	1	PAPER/Molded Pulp		788 g
	Internal:	PLASTIC/Polyethylene low den	sity - LDPE	44 g
Material Usage	This product does not contain any of the following substances in excess of regulatory limits (ref to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics • Cadmium • Chlorinated Hydrocarbons • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead carbonates and sulfates • Lead and Lead compounds • Mercuric Oxide Batteries • Nickel – finishes must not be used on the external surface designed to be frequently handled of carried by the user. • Ozone Depleting Substances		s of regulatory limits (refer f): ardants in plastics	



Features

	Polybrominated Biphenyls (PBBs)
	Polybrominated Biphenyl Ethers (PBBEs)
	Polybrominated Biphenyl Oxides (PBBOs)
	Polychlorinated Biphenyl (PCB)
	Polychlorinated Terphenyls (PCT)
	• Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been
	voluntarily removed from most applications.
	• Radioactive Substances
	• Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	• Design packaging materials for ease of disassembly.
	• Maximize the use of post-consumer recycled content materials in packaging materials.
	• Use readily recyclable packaging materials such as paper and corrugated materials.
	• Reduce size and weight of packages to improve transportation fuel efficiency.
	• Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment. Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf
	_Certificate.pdf and

HP EliteOne 800 G6 23.8-in All-in-One

Eco-Label Certifications & declarations	This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks:
	 IT ECO declaration US ENERGY STAR[®] US Federal Energy Management Program (FEMP) EPEAT^D Gold: Bronze, Silver, Gold registered in the United States. See http://www.epeat.net for registration status in your country. TCO Certified Edge China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label*



Features

System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the All- in-One PC model is based on a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows [®] operating system.				
Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz		100VAC, 50Hz	
Normal Operation (Short idle)	15.60 W	15.68 W		15.45 W	
Normal Operation (Long idle)	5.57 W	5.65 W		5.41 W	
Sleep	0.94 W	1.00	W	0.82 W	
Off	0.84 W	0.87	W	0.81 W	
	NOTE: Energy efficiency data listed is for family. HP computers marked with the El Environmental Protection Agency (EPA) E not offer ENERGY STAR® compliant config configured PC featuring a hard disk drive system.	NERGY STAR® Logo ENERGY STAR® spec gurations, then ene , a high efficiency p	are compliant with cifications for comp ergy efficiency data ower supply, and a	the applicable U.S. outers. If a model family does listed is for a typically Microsoft Windows® operating	
Heat Dissipation*	115VAC, 60Hz	230VAC,	50Hz	100VAC, 50Hz	
Normal Operation (Short idle)	53.2028BTU/hr	53.4772 BTU/hr		52.691 BTU/hr	
Normal Operation (Long idle)	19.02 BTU/hr	19.3 BTU/hr		18.5 BTU/hr	
Sleep	3.2 BTU/hr	3.4 BTU/hr		2.8 BTU/hr	
Off	2.9 BTU/hr	3 BTU/hr		2.8 BTU/hr	
Declared Noise Emissions (in accordance with	NOTE: Heat dissipation is calculated based on the measured watts, assuming the service level is attained for one hour. Sound Power Sound Pressure				
ISO 7779 and ISO 9296)	(L _{WAd} , bels)		(1	_{-pAm} , decibels)	
Typically Configured – Idle	2.5			14	
Fixed Disk – Random writes	2.5			15	
Longevity and Upgrading	 This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: 6 USB ports 2 memory slots 1 Mini PCle half-length slot 1 MXM 3.0 Type A - 35W slot 1 mSATA slot 1 2.5" internal bay supporting up to Two 2.5" hard drives (HDD/SSD/SED/SSHD) 1 5.25" external supporting optical drive Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.				
Batteries	This battery(s) in this product comply Batteries used in the product do not Mercury greater the1ppm by weight Cadmium greater than 20ppm by wei	contain:	e 2006/66/EC		
	Battery size: CR2032 (coin cell) Battery type: Lithium				



- 2011 • This Hi (WEEE • This pr Water • This pr www.e • Plastic ISO104 • This pr <i>1680.</i>	/65/EC. P product is designed to comply with the Waste Electrical a) Directive – 2002/96/EC. roduct is in compliance with California Proposition 65 (Stat and Toxic Enforcement Act of 1986). roduct is in compliance with the IEEE 1680 (EPEAT) standar epeat.net as parts weighing over 25 grams used in the product are ma 43. roduct contains 51.7% post-consumer recycled plastic (by 1-2018 standard, criterion 4.2.1.1.	nd Electronic Equipment e of California; Safe Drinking d at the gold level, see arked per ISO11469 and wt.) <i>according to IEEE</i>		
Futowals	DADED/Communicated	1 400 -		
		1.488 g		
		1.052 g		
HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to o products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.				
elimination of substances of concern. We have supported the inclusion of additional substances— including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products. We met our voluntary objective to achieve worldwide compliance with the new EU RoHS requirements for virtually all relevant products by July 2013, and we will continue to extend the scope of the commitment to include further restricted substances as regulations continue to evolve.				
To obtain a c	opy of the HP RoHS Compliance Statement, see HP RoHS p	osition statement.		
to the HP Ger http://www.l • Asbestos • Certain Azo • Certain Bro • Cadmium • Chlorinatec • Chlorinatec • Formaldeh • Halogenate • Lead carbo • Lead and Le • Mercuric O • Nickel – fini carried by th • Ozone Depl	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pdf): • Asbestos • Certain Azo Colorants • Certain Brominated Flame Retardants – may not be used as flame retardants in plastics			
	 2011 This H (WEEE This p Water This p Water This p Water This p Www.e Plastic ISO104 This p <i>1680.</i> This p The plastic p The corrugat HP Inc. comp restrictions i products wo legislation in We believe the elimination of including PV and electron We met our w requirement scope of the evolve. To obtain a construct to the HP Ge http://www. Asbestos Certain Azo Certain Bro Cadmium Chlorinated Chlorinated Halogenate Lead carbo Lead and Lo Mercuric Os Nickel – fin carried by th Ozone Dep 	1680.1-2018 standard, criterion 4.2.1.1. • This product is 97.8% recycle-able when properly disposed of at External: PAPER/Corrugated Internal: PLASTIC/Polyethylene Expanded - EPE The plastic packaging material contains at least 90% recycled content. The corrugated paper packaging materials contains at least 80% recycl HP Inc. complies fully with materials regulations. We were among the firestrictions in the European Union (EU) Restriction of Hazardous Substaproducts worldwide through the HP GSE. HP has contributed to the devilegislation in Europe, as well as China, India, and Vietnam. We believe the RoHS directive and similar laws play an important role in elimination of substances of concern. We have supported the inclusion including PVC, BFRs, and certain phthalates—in future RoHS legislatior and electronics products. We met our voluntary objective to achieve worldwide compliance with trequirements for virtually all relevant products by July 2013, and we w scope of the commitment to include further restricted substances as reevolve. To obtain a copy of the HP RoHS Compliance Statement, see HP RoHS p This product does not contain any of the following substances in excess to the HP General Specification for the Environment at http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/gse.pd Asbestos Certain Brominated Flame Retardants – may not be used as flame retained and Lead compounds • Cadmium • Chlorinated Paraffins • Formaldehyde • Halogenated Diphenyl Methanes • Lead		



Features

	Polychlorinated Terphenyls (PCT)
	Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been
	voluntarily removed from most applications.
	Radioactive Substances Tributul Tip (TPT) Tributul Tip Ovide (TPTO)
Packaging Usage	• Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaying Usage	HP follows these guidelines to decrease the environmental impact of product packaging:
	• Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials.
	• Eliminate the use of ozone-depleting substances (ODS) in packaging materials.
	• Design packaging materials for ease of disassembly.
	• Maximize the use of post-consumer recycled content materials in packaging materials.
	• Use readily recyclable packaging materials such as paper and corrugated materials.
	Reduce size and weight of packages to improve transportation fuel efficiency.
	 Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner.
	The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
	Global Citizenship Report
	http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications
	http://www8.hp.com/us/en/hp-information/environment/ecolabels.html
	ISO 14001 certificates:
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/PC_GBU_Product_Design_ISO_14K
	_Certificate.pdf
	and
	http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf

HP EliteOne 800 G6 27 All-in-One PC

Eco-Label Certifications & declarations	 This product has received or is in the process of being certified to the following approvals and may be labeled with one or more of these marks: IT ECO declaration US ENERGY STAR[®] US Federal Energy Management Program (FEMP) EPEAT[□] Gold: Bronze, Silver, Gold registered in the United States. See http://www.epeat.net for registration status in your country. TCO Certified Edge China Energy Conservation Program (CECP) China State Environmental Protection Administration (SEPA) Taiwan Green Mark Korea Eco-label Japan PC Green label*
System Configuration	The configuration used for the Energy Consumption and Declared Noise Emissions data for the All- in-One PC model is based on a typically configured PC featuring a hard disk drive, a high efficiency power supply, and a Microsoft Windows® operating system.



Features

Energy Consumption (in accordance with US ENERGY STAR® test method)	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	22.57 W	22.65 W	22.42 W
Normal Operation (Long idle)	6.35 W	6.44 W	6.19 W
Sleep	1.47 W	1.52 W	1.35 W
Off	family. HP computers marked with Environmental Protection Agency not offer ENERGY STAR® compliant	the ENERGY STAR [®] Logo are (EPA) ENERGY STAR [®] specific t configurations, then energy	0.84 W apliant product if offered within the model compliant with the applicable U.S. ations for computers. If a model family does officiency data listed is for a typically er supply, and a Microsoft Windows® operating
Heat Dissipation*	115VAC, 60Hz	230VAC, 50Hz	100VAC, 60Hz
Normal Operation (Short idle)	76.967 BTU/hr	77.2467 BTU/hr	76.4556 BTU/hr
Normal Operation (Long idle)	21.7 BTU/hr	22 BTU/hr	21.2 BTU/hr
Sleep	5 BTU/hr	5.2 BTU/hr	4.6 BTU/hr
Off	3 BTU/hr	3 BTU/hr	2.9 BTU/hr
Declared Noise Emissions (in accordance with ISO 7779 and ISO 9296)	one hour. Sound Power (L _{WAd} , bels)		Sound Pressure (L _{pAm} , decibels)
Typically Configured – Idle	2.5 15		15
Fixed Disk – Random writes			16
Longevity and Upgrading	 This product can be upgraded, possibly extending its useful life by several years. Upgradeable features and/or components contained in the product may include: 6 USB ports 2 memory slots 1 Mini PCIe half-length slot 1 MXM 3.0 Type A - 35W slot 1 mSATA slot 1 2.5" internal bay supporting up to Two 2.5" hard drives (HDD/SSD/SED/SSHD) 1 5.25" external supporting optical drive Spare parts are available throughout the warranty period and or for up to "5" years after the end of production.		
Batteries	This battery(s) in this product c Batteries used in the product de Mercury greater the1ppm by w Cadmium greater than 20ppm l Battery size: CR2032 (coin cell) Battery type: Lithium	o not contain: eight oy weight	006/66/EC



Additional Information	• This product is in compliance with the Restrictions of Hazardous Substances (RoHS) directive - 2011/65/EC.		
	(WE	HP product is designed to comply with the Waste Ele EE) Directive – 2002/96/EC.	
		product is in compliance with California Proposition (king Water and Toxic Enforcement Act of 1986).	55 (State of California; Safe
	www	product is in compliance with the IEEE 1680 (EPEAT) w.epeat.net	-
	ISO1	tics parts weighing over 25 grams used in the produc 1043.	-
	168	product contains 72.2% post-consumer recycled pla 0.1-2018 standard, criterion 4.2.1.1.	
	• This	product is 98% recycle-able when properly disposed	of at end of life.
Packaging Materials	External:	PAPER/Corrugated	1.510 g
	Internal:	PLASTIC/Polyethylene Expanded - EPE	1.520 g
	The plastic p	backaging material contains at least xx% recycled cor	itent.
	The corruga	ted paper packaging materials contains at least xx%	recycled content.
RoHS Compliance	HP Inc. complies fully with materials regulations. We were among the first companies to extend the restrictions in the European Union (EU) Restriction of Hazardous Substances (RoHS) Directive to our products worldwide through the HP GSE. HP has contributed to the development of related legislation in Europe, as well as China, India, and Vietnam.		
	We believe the RoHS directive and similar laws play an important role in promoting industry-wide elimination of substances of concern. We have supported the inclusion of additional substances—including PVC, BFRs, and certain phthalates—in future RoHS legislation that pertains to electrical and electronics products.		
	requirement	voluntary objective to achieve worldwide compliance of s for virtually all relevant products by July 2013, and commitment to include further restricted substances	we will continue to extend the
	To obtain a c	opy of the HP RoHS Compliance Statement, see: HP R	oHS position statement.
Material Usage	to the HP Gei	does not contain any of the following substances in eneral Specification for the Environment at hp.com/hpinfo/globalcitizenship/environment/supply	
	Cert Cert	estos ain Azo Colorants ain Brominated Flame Retardants – may not be used mium	as flame retardants in plastics
	Chlo Chlo	orinated Hydrocarbons orinated Paraffins	
		2-Ethylhexyl) phthalate (DEHP)	
		zyl butyl phthalate (BBP)	
		ityl phthalate (DBP)	
		obutyl phthalate (DIBP)	
		naldehyde Manatod Diabonyl Mathanac	
	 Halo 	ogenated Diphenyl Methanes	
	• Lead	d carbonates and sulfates d and Lead compounds	



Features

	 Nickel – finishes must not be used on the external surface designed to be frequently handled or carried by the user. Ozone Depleting Substances Polybrominated Biphenyls (PBBs) Polybrominated Biphenyl Ethers (PBBEs) Polybrominated Biphenyl Oxides (PBBOs) Polychlorinated Biphenyl (PCB) Polychlorinated Terphenyls (PCT) Polyvinyl Chloride (PVC) – except for wires and cables, and certain retail packaging has been voluntarily removed from most applications. Radioactive Substances Tributyl Tin (TBT), Triphenyl Tin (TPT), Tributyl Tin Oxide (TBTO)
Packaging Usage	 HP follows these guidelines to decrease the environmental impact of product packaging: Eliminate the use of heavy metals such as lead, chromium, mercury and cadmium in packaging materials. Eliminate the use of ozone-depleting substances (ODS) in packaging materials. Design packaging materials for ease of disassembly. Maximize the use of post-consumer recycled content materials in packaging materials. Use readily recyclable packaging materials such as paper and corrugated materials. Reduce size and weight of packages to improve transportation fuel efficiency. Plastic packaging materials are marked according to ISO 11469 and DIN 6120 standards.
End-of-life Management and Recycling	 HP Inc. offers end-of-life HP product return and recycling programs in many geographic areas. To recycle your product, please go to: http://www.hp.com/go/reuse-recycle or contact your nearest HP sales office. Products returned to HP will be recycled, recovered or disposed of in a responsible manner. The EU WEEE directive (2002/95/EC) requires manufacturers to provide treatment information for each product type for use by treatment facilities. This information (product disassembly instructions) is posted on the Hewlett Packard web site at: http://www.hp.com/go/recyclers. These instructions may be used by recyclers and other WEEE treatment facilities as well as HP OEM customers who integrate and re-sell HP equipment.
HP, Inc. Corporate Environmental	For more information about HP's commitment to the environment:
Environmental Information	Global Citizenship Report http://www.hp.com/hpinfo/globalcitizenship/gcreport/index.html Eco-label certifications http://www8.hp.com/us/en/hp-information/environment/ecolabels.html ISO 14001 certificates: http://h20195.www2.hp.com/V2/GetDocument.aspx?docname=c04755842 and http://www.hp.com/hpinfo/globalcitizenship/environment/pdf/cert.pdf



Features

SERVICE AND SUPPORT

HP EliteDesk 800 G6 Tower Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.¹⁸

15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.

18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

HP EliteDesk 800 G6 Small Form Factor Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.¹⁸

15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

 On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
 Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24

x 7 support may not be available in some countries.

18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

HP EliteDesk 800 G6 Desktop Mini Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.¹⁸

15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.

18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.



Features

HP EliteOne 800 G6 24 & 27 All-in-One Business PC

On-site Warranty¹⁵: Three-year (3-3-3) limited warranty delivers three years of on-site, next business day¹⁶ service for parts and labor and includes free support 24 x 7¹⁷. Three-year onsite and labor are not available in all countries. Service offers terms up to 5 years by choosing an optional HP Care Pack. To choose the right level of service for your HP product, visit HP Care Pack Central: http://www.hp.com/go/cpc.¹⁸

15. Terms and conditions may vary by country. Certain restrictions and exclusions apply. Other warranty variations may be offered in your region.

16. On-site service may be provided pursuant to a service contract between HP and an authorized HP third-party provider, and is not available in certain countries. Global service response times are based on commercially reasonable best effort and may vary by country.
17. Technical telephone support applies only to HP-configured and third-party HP qualified hardware and software. Toll-free calling and 24 x 7 support may not be available in some countries.

18. Service levels and response times for HP Care Packs may vary depending on your geographic location. Service starts on date of hardware purchase. Restrictions and limitations apply. For details, visit www.hp.com/go/cpc. HP services are governed by the applicable HP terms and conditions of service provided or indicated to Customer at the time of purchase. Customer may have additional statutory rights according to applicable local laws, and such rights are not in any way affected by the HP terms and conditions of service or the HP Limited Warranty provided with your HP Product.

CERTIFICATION AND COMPLIANCE

Energy Efficiency Compliance

ENERGY STAR[®] certified. EPEAT[®] 2019 registered where applicable. EPEAT [®] registration varies by country. See http://www.epeat.net for registration status by country. According to IEEE 1680.1-2018.



Technical Specifications – Processors

PROCESSORS

Intel[®] 10th Generation Core[™] Processors

All HP EliteDesk 800 G6 Business PC models featuring this technology include processors that are part of the Intel[®] Stable Image Platform Program (SIPP) designed to ensure the stability promise inherent in the value proposition of the HP EliteDesk and EliteOne 800 G6 Business PC.

Intel[®] Advanced Management Technology (AMT) v12 – An advanced set of remote management features and functionality which provides network administrators the latest and most effective tools to remotely discover, heal, and protect networked client systems regardless of the system's health or power state. AMT 12 includes the following advanced management functions:

- Support for configuration of Intel AMT 12.0 new capabilities
- No reset after provisioning
- Support changes to BIOS table 130
- Support for Microsoft Windows Server 2012 R2
- Support for New Microsoft SQL Server Versions including Standard and Enterprise editions
- Support for Intel SSD Prop 2500 Series
- Support for Intel Enterprise Digital Fence
- The Platform Discovery Utility can now discover these additional Intel products:
- Intel SSD Pro 2500 Series; Enterprise Digital Fence
- Intel Identity Protection Technology with One Time Password; Public Key Infrastructure; Multi Factor Authentication
- Intel Identity Protection Technology with Intel WiGig
- New Profile Editor and Profile Editor Plugin Interface
- New Required Permissions for Solutions Framework



Technical Specifications - Display Panel Specifications

DISPLAY PANEL SPECIFICATIONS

23.8" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) non-touch or optional Projected Capacitive Touch supports up to 10 touch-points

Non-Touch Support HW low blue light feature

Туре	IPS WLED Backlit LCD
Active area (mm)	527.04 x 296.46
Native Resolution (HxV)	1920 x 1080
Refresh Rate	60 Hz @ 1920 x 1080
Aspect ratio	16:9
Pixel pitch (HxV)(mm)	0.2745 x 0.2745
Contrast ratio	1000:1
Brightness*	250nits
Viewing angle (HxV)	178°x 178°
Backlight lamp life (to half brightness)	30,000 hours minimum
Color support	Up to 16.7 million colors with the use of FRC technology
Color gamut	NTSC 72%
Anti-glare	Yes*
Response Time	14ms
Default color temperature	Warm (6500K)

NOTE*: Actual brightness will be lower with touchscreen or HP Sure View

23.8" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) with HP Sure View (optional)

-	-
Туре	IPS WLED Backlit LCD
Active area (mm)	527.04 x 296.46
Native Resolution (HxV)	1920 x 1080
Refresh Rate	60 Hz @ 1920 x 1080
Aspect ratio	16:9
Pixel pitch (HxV)(mm)	0.2745 x 0.2745
Contrast ratio	1000:1
Brightness*	285 nits (non-Privacy); 400 nits (Privacy)
Viewing angle (HxV)	178° x 178° (non-Privacy); 80° x 178° (Privacy)
Backlight lamp life (to half brightness)	30,000 hours minimum
Color support	Up to 16.7 million colors with the use of FRC technology
Color gamut	NTSC 72%
Anti-glare	Yes*
Response Time	14ms
Default color temperature	Warm (6500K)

NOTE*: Actual brightness will be lower with touchscreen or HP Sure View



Technical Specifications - Display Panel Specifications

27.0" diagonal IPS widescreen WLED backlit anti-glare LCD (1920 x 1080) non-touch

Support HW low blue light feature	-
Туре	IPS WLED Backlit LCD
Active area (mm)	597.888 x 336.312
Native Resolution (HxV)	1920 x 1080
Refresh Rate	60 Hz @ 1920 x 1080
Aspect ratio	16:9
Pixel pitch (HxV)(mm)	0.3114 x 0.3114
Contrast ratio	1000:1
Brightness	250nits
Viewing angle (HxV)	178° x 178°
Backlight lamp life (to half brightness)	30,000 hours minimum
Color support	Up to 16.7 million colors with the use of FRC technology
Color gamut	NTSC 72%
Anti-glare	Yes*
Response Time	14ms
Default color temperature	Warm (6500K)

27.0" diagonal IPS widescreen WLED backlit LCD (2560 x 1440) Touch

Support HW low blue light feature	
Туре	IPS WLED Backlit LCD
Active area (mm)	596.736 x 335.664
Native Resolution (HxV)	2560 x 1440
Refresh Rate	60 Hz @ 1920 x 1080
Aspect ratio	16:9
Pixel pitch (HxV)(mm)	0.2331 x 0.2331
Contrast ratio	1000:1
Brightness*	300nits
Viewing angle (HxV)	178° x 178°
Backlight lamp life (to half brightness)	30,000 hours minimum
Color support	Up to 16.7 million colors with the use of FRC technology
Color gamut	NTSC 72%
Anti-glare	No*
Response Time	14ms
Default color temperature	Warm (6500K)

1. All performance specifications represent the typical specifications provided by HP's component manufacturers; actual performance may vary either higher or lower.

2. For All in One only Intel® HD Graphics (integrated)

NOTE*: Actual brightness will be lower with touchscreen or HP Sure View



Technical Specifications – Display Panel Specifications

Adjustable Height Stand:	Height - Vertical/Landscape Adjustment	130mm (±2 mm)
	Portrait Adjustment	No portrait
	Tilt Angle	-5° to +18° (±2°) in landscape and portrait
	Rotation (Swivel)	90° (±1°) (45 left, 45 right)
	Pivot	No pivot
Recline Stand:	Height - Vertical Adjustment	No height
	Tilt Angle	+36.5° to +58° (+/-1.5°)
	Rotation (swivel)	No swivel



GRAPHICS

HP EliteDesk 800 G6 Desktop Mini Business PC

Intel [®] HD Graphics (integrated)	
VGA Controller	Integrated
	Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-
DisplayPort™	Stream Technology for a maximum of 3 displays connected to any output controlled by Intel®
	Graphics
	Supports HDMI 2.0a features
HDMI (optional)	Supports HDCP 2.3
-	Supports audio over HDMI
VGA (optional)	VGA output
USB-C [®] DP Alt Mode (optional)	DisplayPort over the optional USB-C [®] module
	The actual amount of maximum graphics memory can be >4GB. System memory is allocated
Memory	for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an
	optimal balance between graphics and system memory use.
Maximum Color Depth	up to 10 bits/color
	HEVC 10b Enc/Dec HW
	VP9 10b Dec HW
Graphics/Video API Support	HDR
	Rec. 2020
	DX12
Max. Resolution (VGA)	2048 x 1536@60Hz
Max. Resolution (HDMI)	4096 x 2160@60Hz
Max. Resolution (DP)	4096 x 2160@60Hz

Nvidia[®] GeFORCE[®] GTX1660 Ti

Architecture	Discrete GPU Nvidia® GPU drives the integrated panel and all of the graphics output ports
DisplayPort	Maximun pixel clock :1.3 GHz pixels per second Maximun bandwidth :25.92 Gbps per connector (FEC Disable)
HDMI	Supports HDMI 2.0 features Supports HDCP 2.2, HDR
Memory	6GByte, 192bit wide GDDR6
Maximum Color Depth	up to 12 bits/color
Graphics/Video API Support	DirectX 12 OpenGL 4.6
Display Port	Support DP1.4(DSC1.2a) Maximum pixel clock :1.3 GHz pixels per second Maximum bandwidth :25.92 Gbps per connector (FEC Disable)
Max. Resolution (HDMI)	4096 x 2160@60Hz
Max. Resolution (DP)	5120 x 3200@60Hz Example of maximum resolutions with CVT-RB timings
Port Availability	(3) Mini DP 1.4 ports and (1) Micro HDMI 2.0 port



HP EliteDesk 800 G6 Tower Business PC

Intel [®] UHD Graphics (integrated)
VGA Controller	Integrated
	Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-
DisplayPort™ 1.4	Stream Technology for a maximum of 3 displays connected to any output controlled by Intel®
	Graphics
	Supports HDMI 2.0a features
HDMI (optional)	Supports HDCP 2.2
	Supports BT2020 and HDR playback (7th Gen processors only)
VGA (optional)	VGA ouput
USB-C [®] DP Alt Mode (optional)	DisplayPort over the optional USB-C [®] module
M	The actual amount of maximum graphics memory can be >4GB. System memory is allocated
Memory	for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Color Depth	up to 10 bits/color
Maximum cotor Depth	HEVC 10b Enc/Dec HW
	VP9 10b Dec HW
Graphics/Video API Support	HDR
	Rec. 2020
	DX12
	640x480 60 Hz640x480 67Hz
	640x480 72Hz
	640x480 75Hz
	720x400 70Hz
	800x600 60Hz
	800x600 75Hz
	1024x768 60Hz
34" UHD Supported	1024x768 75Hz
Resolutions and Refresh	1280x960 60Hz
Rates. Other resolutions may also work.	1280x720 60Hz
also work.	1280x1024 60Hz 1280x1024 75Hz
	1440x900 60Hz
	1440x900 75Hz
	1680x1050 60Hz
	1920x1080 60Hz
	3440x1440 60Hz (Native Resolution)
	3440x1440 30Hz
Max. Resolution (VGA)	2048 x 1536@60Hz
Max. Resolution (HDMI)	4096 x 2160@60Hz
Max. Resolution (DP)	4096 x 2160@60Hz
NVIDIA® GeForce® RTX 2060 S	Super 8GB Graphics Card
Engine Clock	1650 MHz
Memory Clock	7000 MHz
Memory Size(width)	8 GB(256-bit)
Memory Type	256M x 32 GDDR6
Max. Resolution(DVI)	2560x1600@60Hz
Max. Resolution(HDMI)	4096x2160@60Hz
Max. Resolution(DP)	7680x4320@60Hz
Multi Display Support	3 displays
HDCP Compliance	Yes

Technical Specifications – Graphics

Rear I/O connectors(bracket)	DVI+HDMI+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<175W
PCB form-factor with bracket	ATX (Full height) PCB with ATX dual slot bracket

AMD® Radeon™ RX 550X 4 GB FH PCIe x16

Engine Clock	1183MHz
Memory Clock	6 Gbps
Memory Size(width)	4 GB(128-bit)
Memory Type	GDDR5
Max. Resolution(HDMI)	4096x2160 @ 60Hz
Max. Resolution(DP)	5120x2880 @ 60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	HDMI, DPx2
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP (low profile) PCB with FH/LP bracket

AMD® Radeon™ RX 580 8GB GDDR5 Graphics Card

	•
Engine Clock	1266 MHz
Memory Clock	4000 MHz
Memory Size(width)	8 GB (256-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(HDMI)	4096x2160@60Hz
Max. Resolution(DP)	5120x3200@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	HDMI + DPx3
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<150W
PCB form-factor with bracket	ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® GeForce® RTX 2080 Super 8GB GDDR6

Engine Clock	1815 MHz
Memory Clock	7750 MHz
Memory Size(width)	8GB (256-bit)
Memory Type	256M x 32 GDDR6
Max. Resolution(Virtual Link)	3840 x 2160@60Hz
Max. Resolution(HDMI)	4096 x 2160@60Hz
Max. Resolution(DP)	7680 x 4320@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	DPx3 + HDMI + Virtual Link



Technical Specifications – Graphics

Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<285W
PCB form-factor with bracket	ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® GeForce® RTX 2070 Super 8GB GDDR6

Engine Clock	1620 MHz
Memory Clock	7000 MHz
Memory Size(width)	8GB (256-bit)
Memory Type	256M x 32 GDDR6
Max. Resolution(Virtual Link)	3840 x 2160@60Hz
Max. Resolution(HDMI)	4096 x 2160@60Hz
Max. Resolution(DP)	7680 x 4320@60Hz
HDCP Compliance	Yes
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<210W
PCB form-factor with bracket	ATX (Full height) PCB with ATX dual slot bracket

NVIDIA® Quadro P620 2GB Graphics Card

Engine Clock	1354 MHz
Memory Clock	2500 MHz
Memory Size(width)	2GB (128-bit)
Memory Type	128M x 32 GDDR5
Max. Resolution(DP)	5120x2880@60Hz
Multi Display Support	4 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	mDPx4
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<40W
PCB form-factor with bracket	LP PCB with LP bracket

NVIDIA® Quadro P400 2GB Graphics Card

,	
Engine Clock	1252 MHz
Memory Clock	2000 MHz
Memory Size(width)	2GB (64-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(DP)	5120x2880@60Hz
Multi Display Support	3 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	mDPx3
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<30W
PCB form-factor with bracket	LP PCB with LP bracket

AMD® Radeon™ R7 430 2GB VGA+DP 64bit Graphics Card



Technical Specifications – Graphics

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	2 GB(64-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(HDMI)	2048x1536
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	VGA+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

AMD® Radeon™ R7 430 2GB GDDR5 2DP 64 bit Graphics Card

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	2 GB(64-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	yes
Rear I/O connectors(bracket)	DPx2
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

HP EliteDesk 800 G6 Small Form Factor Business PC

Intel [®] HD Graphics (integrated)	
VGA Controller	Integrated
DisplayPort™ 1.4	Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-Stream Technology for a maximum of 3 displays connected to any output controlled by Intel® Graphics
HDMI (optional)	Supports HDMI 2.0a features Supports HDCP 2.2 Supports audio over HDMI
VGA (optional)	VGA Output
USB-C [®] DP Alt Mode (optional)	DisplayPort over the optional USB-C [®] module
Memory	The actual amount of maximum graphics memory can be >4GB. System memory is allocated for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Color Depth	up to 10 bits/color
Graphics/Video API Support	HEVC 10b Enc/Dec HW VP9 10b Dec HW HDR Rec. 2020 DX12
Max. Resolution (VGA)	2048 x 1536@60Hz
Max. Resolution (HDMI)	4096 x 2160@60Hz
Max. Resolution (DP)	4096 x 2160@60Hz



AMD[®] Radeon[™] R7 430 2GB VGA+DP 64bit Graphics Card

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	1 GB(64-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(HDMI)	2048x1536
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	VGA+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

AMD® Radeon™ R7 430 2GB GDDR5 2DP 64 bit Graphics Card

	•
Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	1 GB(64-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(DP)	4096x2160@60Hz
Multi Display Support	2 displays
HDCP Compliance	yes
Rear I/O connectors(bracket)	DPx2
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket

AMD® Radeon™ RX550 4 GB PCIe x16	
Engine Clock	1183MHz
Memory Clock	6 Gbps
Memory Size(width)	4 GB(128-bit)
Memory Type	GDDR5
Max. Resolution(HDMI)	4096x2160 @ 60Hz
Max. Resolution(DP)	5120x2880 @ 60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	HDMI, DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP (low profile) PCB with FH/LP bracket



AMD Radeon™ 520 1GB Graphics Card

Engine Clock	780 MHz
Memory Clock	1100 MHz
Memory Size(width)	1 GB (32-bit)
Memory Type	256M x 32 GDDR5
Max. Resolution(DP)	2048x1536@60Hz
Multi Display Support	2 displays
HDCP Compliance	Yes
Rear I/O connectors(bracket)	VGA+DP
Cooling(active/passive)	Active fan-sink (Active cooling with dynamic speed)
Total power consumption(W)	<50W
PCB form-factor with bracket	LP PCB with FH/LP bracket



HP EliteOne 800 G6 23.8-in All-in-One

Intel [®] UHD Graphics (integrated)	
VGA Controller	Integrated
	Multimode capable; supports HDCP, Display Port Audio (2 streams), HBR2 link rates and Multi-
DisplayPort™ 1.4	Stream Technology for a maximum of 3 displays (including the integrated panel and all
HDMI-in	attached displays) Support HDMI-In
	The actual amount of maximum graphics memory can be >4GB. System memory is allocated
Memory	for graphics as needed using Intel's Dynamic Video Memory Technology (DVMT), to provide an optimal balance between graphics and system memory use.
Maximum Color Depth	up to 10 bits/color HEVC 10b Enc/Dec HW
	VP9 10b Dec HW
Graphics/Video API Support	HDR
	Rec. 2020 DX12
Max. Resolution (VGA)	2048 x 1536@60Hz
Max. Resolution (HDMI)	4096 x 2160@60Hz
· · · · · ·	-
Max. Resolution (DP)	4096 x 2160@60Hz
AMD® R19M	
Architecture	Discrete GPU AMD® GPU drives the integrated panel and all of the graphics output ports
DisplayPort	Multimode capable; supports HDCP, HDR, Display Port Audio (6 streams max), DisplayPort HBR3 link rates and Multi-Stream Technology for a maximum of 5 3 displays (including the integrated panel and all attached displays)
HDMI-In	Support HDMI-In
Memory	3GByte, 128bit wide GDDR6
Maximum Color Depth	up to 12 bits/color
Graphics/Video API Support	DirectX 12
	OpenCL 2.0 OpenGL 4.5 AMD® Unified Video Decoder (UVD)
Max. Resolution (DP)	4096 x 2160@60Hz
Nvidia ® N18E-G2R	
Architecture	Discrete GPU NVidia® GPU drives the integrated panel and all of the graphics output ports
DisplayPort	Multimode capable; supports HDCP, HDR, Display Port Audio (6 streams max), DisplayPort HBR3 link rates and Multi-Stream Technology for a maximum of 3 displays (including the integrated panel and all attached displays)
HDMI-In	Support HDMI-In
Memory	8GByte, 128bit wide GDDR6
-	up to 12 bits/color
Graphics/Video API Support	DirectX 12
	OpenCL 2.0
	OpenGL 4.5
Max. Resolution (DP)	4096 x 2160@60Hz



Technical Specifications – Storage

STORAGE

500 GB 7200RPM 3.5in SATA HDD	
Capacity	500 GB
Rotational Speed	7,200 rpm
Interface	SATA 6.0 Gb/s
Buffer Size	32 MB
Logical Blocks	976,773,168
Seek Time	11 ms (Average)
Height	1 in/2.54 cm
Width	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB 7200RPM 3.5in SATA HDD

Capacity	1 TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	64 MB
Logical Blocks	1,953,525,168
Seek Time	11 ms (Average)
Height	1 in/2.54 cm
Width (nominal)	Media diameter: 3.5 in/8.89 cm Physical size: 4 in/10.2 cm
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB 7200RPM 3.5in SATA HDD

Capacity	2 TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	128 MB
Logical Blocks	3,907,050,336
Seek Time	11 ms (Average)
Height	1.028 in/26.11 mm
Width (nominal)	Media diameter: 3.5 in/88.9 mm Physical size: 4 in/102 mm
Operating Temperature	41° to 131° F (5° to 55° C)



500 GB 7200RPM 2.5in SATA HDD

Capacity	500 GB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	Up to 128 MB
Logical Blocks	976,773,168
Seek Time	11 ms (Average)
Height	0.283 in/7.2 mm (Max.)
Width (nominal)	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB 7200RPM 2.5in SATA HDD

Capacity	1 TB
Rotational Speed	7,200 rpm
Interface	SATA 6 Gb/s
Buffer Size	Up to 128 MB
Logical Blocks	1,953,525,168
Seek Time	11 ms (Average)
Height	0.374 in/9.5 mm (nominal)
Width (nominal)	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB 5400RPM 2.5in SATA HDD

Capacity	2 TB
Rotational Speed	5,400 rpm
Interface	SATA 6 Gb/s
Buffer Size	128 MB
Logical Blocks	3,907,050,336
Seek Time	11 ms (Average)
Height	0.374 in/9.5 mm (nominal)
Width (nominal)	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)



500 GB 7200RPM 2.5in Self Encrypted OPAL2 SATA HDD

Capacity	500 GB
Architecture	Self-Encrypting (SED) Solid State Drive with SATA interface
Interface	SATA 6 Gb/s
Buffer Size	128 MB
Logical Blocks	976,773,168
Seek Time	11 ms (Average)
Height	0.283 in/7.2 mm (nominal)
Width	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

500 GB 7200RPM 2.5in Self Encrypted Federal Information Processing Standard SATA HDD

Capacity	500 GB
Architecture	Self-Encrypting (SED) Solid State Drive with SATA interface
Interface	SATA 6 Gb/s
Buffer Size	128 MB
Logical Blocks	976,773,168
Seek Time	11 ms (Average)
Height	0.283 in/7.2 mm (nominal)
Width	2.75 in/70 mm (nominal)
Operating Temperature	41° to 131° F (5° to 55° C)

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	256 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 780MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2



512 GB M.2 2280 PCIe NVMe SSD

Drive Weight	< 10g
Capacity	512 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 1600MB/s
Maximum Sequential Write	Up to 860MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

128 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	128 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 2800MB/s
Maximum Sequential Write	Up to 600MB/s
Logical Blocks	250,069,680
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	256GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 2700MB/s
Maximum Sequential Write	Up to 1000MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2



512 GB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	512 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

1 TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	1 TB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 3480MB/s
Maximum Sequential Write	Up to 3037MB/s
Logical Blocks	2,000,409,264
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

2 TB M.2 2280 PCIe NVMe Three Layer Cell SSD

Drive Weight	< 10g
Capacity	2 TB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 3500MB/s
Maximum Sequential Write	Up to 3000MB/s
Logical Blocks	3,907,029,168
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; ASPM L1.2



256 GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight	< 10g
Capacity	256 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 2700MB/s
Maximum Sequential Write	Up to 1000MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

512 GB M.2 2280 PCIe NVMe Self Encrypted OPAL2 Three Layer Cell SSD

Drive Weight	< 10g
Capacity	512 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIE Gen3
Maximum Sequential Read	Up to 2900MB/s
Maximum Sequential Write	Up to 1100MB/s
Logical Blocks	1,000,215,216
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	APST; ASPM L1.2; NVME spec 1.2; TCG-OPAL2 security

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

256 GB Intel[®] PCIe[®] NVMe[™] QLC + 32 GB Intel[®] Optane[™]

Drive Weight	< 10g
Capacity	256 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCle Gen3
Maximum Sequential Read	Up to 1450MB/s
Maximum Sequential Write	Up to 500MB/s
Logical Blocks	500,118,192
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; ASPM L1.2



512 GB Intel® PCIe® NVMe™ QLC + 32 GB Intel® Optane™

Drive Weight	< 10g
Capacity	512 GB
Height	2.38mm
Length	80mm
Width	22mm
Interface	PCIe Gen3
Maximum Sequential Read	Up to 2400MB/s
Maximum Sequential Write	Up to 1300MB/s
Logical Blocks	1,000,215,215
Operating Temperature	0° to 70°C (32° to 158°F) [ambient temp]
Features	TRIM; ASPM L1.2

NOTE: For hard drives and solid state drives, GB = 1 billion bytes. TB = 1 trillion bytes. Actual formatted capacity is less. Up to 36 GB (for Windows 10) of system disk is reserved for the system recovery software.

HP 9.5mm Slim DVD-ROM Drive

Height	9.5 mm height
Orientation	Either horizontal or vertical
Interface type	SATA/ATAPI
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel
Weight (max)	Up to 0.31 lb (140g) without bezel
Read Speeds	DVD+R/-R/+RW/ -RW/+R DL /-R DL Up to 8X DVD-ROM Up to 8X CD-ROM, CD-R Up to 24X CD-RW Up to 24X
Access time (typical reads, including settling)	Random: DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full stroke: DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical)
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Slim DVD Writer Drive

Height	9.5 mm height	
Orientation	Either horizontal or vertical	
Interface type	SATA/ATAPI	
Disc recording capacity	Up to 8.5 GB DL or 4.7 GB standard	
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel	
Weight (max)	0.31 lb (140 g)	
Write Speeds	DVD-R DL - Up to 6X	
	DVD+R - Up to 8X	
	DVD+RW - Up to 8X	



	DVD+R DL - Up to 6X DVD-R - Up to 8X DVD-RW - Up to 6X CD-R - Up to 24X CD-RW - Up to 10X DVD-RW, DVD+RW - Up to 8X
Read Speeds	DVD-R DL, DVD+R DL - Up to 8X DVD+R, DVD-R - Up to 8X DVD-ROM DL, DVD-ROM - Up to 8X CD-ROM, CD-R - Up to 24X CD-RW - Up to 24X
Access time (typical reads, including settling)	Random DVD-ROM: 170 ms (typical), CD-ROM: 170 ms (typical) Full Stroke DVD-ROM: 320 ms (typical), CD-ROM: 320 ms (typical) Stop Time 6 seconds (typical)
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC (< 1000 mA typical, 1600 mA maximum)
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

HP 9.5mm Slim Blu-Ray Writer Drive

···· •••••••••••••••••••••••••••••••••			
Height	9.5 mm height		
Orientation	Either horizontal or vertical		
Interface type	SATA/ATAPI		
Disc recording capacity	Up to 128 GB QL, 100 GB TL, 50 GB DL or 25 GB standard SL		
Dimensions (W x H x D)	5.04 x 0.37 x 5.0 in (128 x 9.5 x 127 mm) without bezel		
Weight (max)	0.29 lb (132 g)		
Write Speeds	BD-R SL/DL Up to 6X BD-R TL/QL Up to 4X BD-R Up to 6X BD-RE Up to 2X DVD-R Up to 8X DVD-R DL - Up to 6X DVD-RW Up to 6X DVD+R Up to 8X DVD+R DL - Up to 6X DVD+R Up to 8X DVD+RW Up to 8X DVD-RAM Up to 5X CD-R Up to 24X CD-RW Up to 10X		
Read Speeds	BD-ROM Up to 6X BD-R Up to 6X BD-RE SL/DL Up to 6X BD-RE TL Up to 4X DVD-ROM Up to 8X DVD-R SL/DL Up to 8X DVD-R Up to 8X DVD-RW Up to 8X DVD+R SL/DL Up to 8X DVD+R Up to 8X		



	BDMV (AACS Compliant Disc) Up to 6x/2x (Read/Play) DVD-RAM Up to 5x DVD-Video (CSS Compliant Disc) Up to 8x/4x (Read/Play) CD-R/RW/ROM Up to 24x CD-DA (DAE) Up to 24X/10X (Read/Play)
Access time (typical reads, including settling)	Random BD-ROM: 205 ms (typical), DVD-ROM: 185 ms (typical), CD-ROM: 165 ms (typical) Full Stroke BD-ROM: 350 ms (typical), DVD-ROM: 345 ms (typical), CD-ROM: 340 ms (typical)
Power	Source Slimline SATA DC power receptacle DC Power Requirement 5 VDC ± 5%-100 mV ripple p-p DC Current 5 VDC -1200 mA typical, 2000 mA maximum
Environmental conditions (operating - non-condensing)	Temperature 41° to 122° F (5° to 50° C) Relative Humidity 10% to 80% Maximum Wet Bulb Temperature 84° F (29° C)

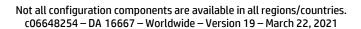
NETWORKING AND COMMUNICATIONS

System Interface Data rates supported	RJ-45 PCI (Intel proprietary) + SMBus
Data rates supported	PCI (Intel proprietary) + SMBus
Data rates supported	
	1. 10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
	2. 100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)
	3. 1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 802.3 clauses 40)
	4. 2.5 Gbit/s operation(2.5GBASE-T; IEEE 802.3bz Clause 126)
	5. Auto-Negotiation (Automatic Speed Selection)
	Full Duplex Operation at all Speeds, Half Duplex operation at 10, 100 & 1000 Mbit/s
EEE Compliance	IEEE 802.1p QoS (Quality of Service) Support
	IEEE 802.1q VLAN support
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)
	IEEE 802.3az EEE (Energy Efficient Ethernet)
	IEEE 802.3i 10BASE-T
	IEEE 802.3u 100BASE-TX
	IEEE 802.3ab 1000BAE-T
	IEEE 802.3bz 2.5GBASE-T
Performance	TCP/IP/UDP Checksum Offload (configurable)
	Protocol Offload (ARP & NS)
	Large send offload and Giant send offload
	Receiving Side Scaling
	Jumbo Frame 9K
Power consumption	Cable Disconnetion: 25mW
	100Mbps Full Run: 450mW
	1000bp Full Run: 1000mW
	WoL Enable(S3/S4/S5): 50mW
	WoL Disable(S3/S4/S5): 25mW
Power	ACPI compliant – multiple power modes
Management	Situation-sensitive features reduce power consumption
	Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection



IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only)
PXE 2.1 Remote Boot	
	Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30))
	Comprehensive diagnostic and configuration software suite
	Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel® i219LM 10/100/10	DO Integrated NIC
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
	100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)
	1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)
	Auto-Negotiation (Automatic Speed Selection)
	Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support
	IEEE 802.1q VLAN support
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)
	IEEE 802.3az EEE (Energy Efficient Ethernet)
Performance	TCP/IP/UDP Checksum Offload (configurable)
	Protocol Offload (ARP & NS)
	Large send offload and Giant send offload
	Receiving Side Scaling
	Jumbo Frame 9K
Power consumption	Cable Disconnetion: 25mW
	100Mbps Full Run: 450mW
	1000bp Full Run: 1000mW
	WoL Enable(S3/S4/S5): 50mW
	WoL Disable(S3/S4/S5): 25mW
Power	ACPI compliant – multiple power modes
Management	Situation-sensitive features reduce power consumption
	Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection





IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-on-LAN from off (Magic Packet only) PXE 2.1 Remote Boot Statistics Gathering (SNMP MIB II, Ethernet-like MIB, Ethernet MIB (802.3x, clause 30)) Comprehensive diagnostic and configuration software suite
	Virtual Cable Doctor for Ethernet cable status
Security & Manageability	Intel® vPro™ support with appropriate Intel® chipset components

Intel® i210 10/100/1000 I	
Connector	RJ-45
System Interface	PCI (Intel proprietary) + SMBus
Data rates supported	10 Mbit/s operation (10BASE-T; IEEE 802.3i; IEEE 802.3 clauses 13-14)
	100 Mbit/s operation (100BASE-TX; IEEE 802.3u; IEEE 802.3 clauses 21-30)
	1000 Mbit/s operation (1000BASE-T; IEEE 802.3ab; IEEE 8023 clauses 40)
	Auto-Negotiation (Automatic Speed Selection)
	Full Duplex Operation at all Speeds, Half Duplex operation at 10 and 100 Mbit/s
IEEE Compliance	IEEE 802.1p QoS (Quality of Service) Support
	IEEE 802.1q VLAN support
	IEEE 802.3x Flow Control (IEEE 802.3 clauses 31-32; configurable)
	IEEE 802.3az EEE (Energy Efficient Ethernet)
Performance	TCP/IP/UDP Checksum Offload (configurable)
	Protocol Offload (ARP & NS)
	Large send offload and Giant send offload
	Receiving Side Scaling
	Jumbo Frame 9K
Power consumption	Cable Disconnetion: 25mW
	100Mbps Full Run: 450mW
	1000bp Full Run: 1000mW
	WoL Enable(S3/S4/S5): 50mW
	WoL Disable(S3/S4/S5): 25mW
Power	ACPI compliant – multiple power modes
Management	Situation-sensitive features reduce power consumption
	Advanced link down power saving for reducing link down power consumption
Management Interface	Auto MDI/MDIX Crossover cable detection
IT Manageability	Wake-on-LAN from standby and hibernation (Magic Packet and Microsoft Wake-Up Frame); Wake-
	on-LAN from off (Magic Packet only)
Security & Manageability	PXE 2.1 Remote Boot

Intel Wi-Fi 6 AX201 + BT5 (8	302.11ax 2x2, vPro, supporting gigabit file transfer speeds) vPro	
Wireless LAN Standards	IEEE 802.11a	
	IEEE 802.11b	
	IEEE 802.11g	
	IEEE 802.11n	
	IEEE 802.11ac	
	IEEE 802.11ax	
	IEEE 802.11d	
	IEEE 802.11e	
	IEEE 802.11h	
	IEEE 802.11i	
	IEEE 802.11k	



	IEEE 802.11r	
	IEEE 802.11v	
Interoperability	Features Wi-Fi 6 technology	
Frequency Band	802.11b/g/n/ax	
	• 2.402 – 2.482 GHz	
	802.11a/n/ac/ax	
	• 4.9 – 4.95 GHz (Japan)	
	• 5.15 – 5.25 GHz	
	• 5.25 – 5.35 GHz	
	• 5.47 – 5.725 GHz	
	• 5.825 – 5.850 GHz	
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps	
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps	
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)	
	 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) 	
	 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) 	
Modulation	Direct Sequence Spread Spectrum	
	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM	
Security ³	 IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only 	
	AES-CCMP: 128 bit in hardware	
	• 802.1x authentication	
	 WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. 	
	WPA2 certification	
	• IEEE 802.11i	
	• WAPI	
Network Architecture	Ad-hoc (Peer to Peer)	
Models	Infrastructure (Access Point Required)	
Roaming	IEEE 802.11 compliant roaming between access points	
Output Power ²	• 802.11b : +18.5dBm minimum	
	• 802.11g : +17.5dBm minimum	
	• 802.11a : +18.5dBm minimum	
	• 802.11n HT20(2.4GHz) : +15.5dBm minimum	
	• 802.11n HT40(2.4GHz) : +14.5dBm minimum	
	• 802.11n HT20(5GHz) : +15.5dBm minimum	
	• 802.11n HT40(5GHz) : +14.5dBm minimum	
	• 802.11ac VHT80(5GHz) : +11.5dBm minimum	
	• 802.11ac VHT160(5GHz) : +11.5dBm minimum	
	• 802.11ax HT40(2.4GHz) : +10dBm minimum	
	• 802.11ax VHT160(5GHz) : +10dBm minimum	
Power Consumption	• Transmit mode: 2.0 W	
	• Receive mode: 1.6 W	
	Idle mode (PSP) 180 mW (WLAN Associated)	
	Idle mode: 50 mW (WLAN unassociated)	
	Connected Standby: 10mW	
D M	Radio disabled: 8 mW	
Power Management	ACPI and PCI Express compliant power management	
	802.11 compliant power saving mode	
Receiver Sensitivity ³	•802.11b, 1Mbps : -93.5dBm maximum	
	•802.11b, 11Mbps : -84dBm maximum	
	• 802.11a/g, 6Mbps : -86dBm maximum	
	• 802.11a/g, 54Mbps : -72dBm maximum	
	• 802.11n, MCS07 : -67dBm maximum	
	• 802.11n, MCS15 : -64dBm maximum	
	• 802.11ac, MCS0 : -84dBm maximum	



	002.11	
	 802.11ac, MCS9 : -59dBm maximum 802.11ax, MCS11(HT40): -59dBm maximum 	
Antonio turo		VHT160): -58.5dBm maximum
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN MIMO communications and Bluetooth communications	
Form Factor		niCard with CNVi Interface
Dimensions	1. Type 2230 : 2.3 x	
	2. Type 1216: 1.67	
Weight	1. Type 2230 : 2.8g	
_	2. Type 126: 1.3g	
Operating Voltage	3.3v +/- 9%	
Temperature	Operating	14° to 158° F (–10° to 70° C)
_	Non-operating	–40° to 176° F (–40° to 80° C)
Humidity	Operating	10% to 90% (non-condensing)
	Non-operating	5% to 95% (non-condensing)
Altitude	Operating	0 to 10,000 ft (3,048 m)
	Non-operating	0 to 50,000 ft (15,240 m)
LED Activity	LED Amber – Radio	o OFF; LED White – Radio ON
HP Integrated Module with Bluet	tooth [®] 4.0/4.1/4.2/	/5.0/5.1 Wireless Technology
Bluetooth [®] Specification	4.0/4.1/4.2/5.0/5.1 Compliant	
Frequency Band	2402 to 2480 MHz	
Number of Available Channels	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)	
Data Rates and Throughput	Legacy : 3 Mbps data	a rate; throughput up to 2.17 Mbps
	BLE : 1 Mbps data rate; throughput up to 0.2 Mbps	
	-	
	Legacy : Synchronous Connection Oriented links up to 3, 64 kbps, voice channels. Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) 864 kbps symmetric (3-EV5)	
Transmit Power		nponent shall operate as a Class II Bluetooth® device with a maximum
		9.5 dBm for BR and EDR.
Power Consumption	Peak (Tx) 330 mW	
-	Peak (Rx) 230 mW	
	Selective Suspend 1	7 mW
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software	
Power Management	Microsoft Windows ACPI, and USB Bus Support	
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249	
Certifications	FUC (47 CFR) Part 15	c, Section 15.247 & 15.249
Power Management Certifications	ns ETS 300 328, ETS 300 826	
	Low Voltage Directive IEC950	
	UL, CSA, and CE Marl	< .
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Co	mpliance
	LE Link Layer Ping	
	LE Dual Mode	
	LE Link Layer	
	LE Link Layer LE Low Duty Cycle D	
	LE Link Layer	n Oriented Channels

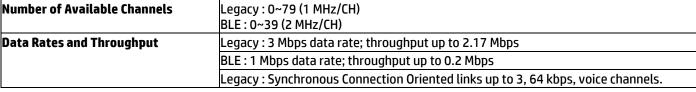


BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP)
Advanced Audio Distribution Profile (A2DP) Intel® vPro™ support with appropriate Intel® chipset components

Intel Wi-Fi 6 AX201 + BT5 (802.11ax 2x2, non-vPro, supporting gigabit file transfer speeds) non-vPro			
Wireless LAN Standards	IEEE 802.11a		
	IEEE 802.11b		
	IEEE 802.11g		
	IEEE 802.11n		
	IEEE 802.11ac		
	IEEE 802.11ax		
	IEEE 802.11d		
	IEEE 802.11e		
	IEEE 802.11h		
	IEEE 802.11i		
	IEEE 802.11k		
	IEEE 802.11r		
	IEEE 802.11v		
Interoperability	Features Wi-Fi 6 technology		
Frequency Band	802.11b/g/n/ax		
	• 2.402 – 2.482 GHz		
	802.11a/n/ac/ax		
	• 4.9 – 4.95 GHz (Japan)		
	• 5.15 – 5.25 GHz		
	• 5.25 – 5.35 GHz		
	• 5.47 – 5.725 GHz		
	• 5.825 – 5.850 GHz		
Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps		
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz)		
	 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz) 		
	• 802.11ax : MCS0 ~ MCS11, (1SS and 2SS) (20MHz, 40MHz, ,80MHz & 160MHz)		
Modulation	Direct Sequence Spread Spectrum		
	OFDM, BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM, 1024QAM		
Security ³	 IEEE compliant 64 / 128 bit WEP encryption for a/b/g mode only 		
	AES-CCMP: 128 bit in hardware		
	802.1x authentication		
	• WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES.		
	WPA2 certification		
	• IEEE 802.11i		
	• WAPI		
Network Architecture	Ad-hoc (Peer to Peer)		
Models	Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between access points		
Output Power ²	• 802.11b : +18.5dBm minimum		
	• 802.11g : +17.5dBm minimum		



·	2			
	• 802.11a : +18.50	JBm minimum		
	• 802.11n HT20(2	.4GHz) : +15.5dBm minimum		
	• 802.11n HT40(2	• 802.11n HT40(2.4GHz) : +14.5dBm minimum		
	• 802.11n HT20(5	GHz) : +15.5dBm minimum		
	• 802.11n HT40(5	GHz) : +14.5dBm minimum		
	• 802.11ac VHT80)(5GHz) : +11.5dBm minimum		
	• 802.11ac VHT16	60(5GHz) : +11.5dBm minimum		
	• 802.11ax HT40(2.4GHz) : +10dBm minimum			
	• 802.11ax VHT160(5GHz) : +10dBm minimum			
Power Consumption	Transmit mode 2.0 W			
	Receive mode 1.6 W			
	 Idle mode (PSP) 	180 mW (WLAN Associated)		
	 Idle mode 50 mV 	N (WLAN unassociated)		
	 Connected Stand 	Jby 10mW		
	 Radio disabled 8 	b mW		
Power Management	ACPI and PCI Expre	ess compliant power management		
	802.11 compliant	power saving mode		
Receiver Sensitivity ³	•802.11b, 1Mbps : -93.5dBm maximum			
	•802.11b, 11Mbps	s : -84dBm maximum		
	• 802.11a/g, 6Mbr	ps : -86dBm maximum		
		bps : -72dBm maximum		
	• 802.11n, MCS07 : -67dBm maximum			
	• 802.11n, MCS15 : -64dBm maximum			
	• 802.11ac, MCS0 : -84dBm maximum			
	• 802.11ac, MCS9	: -59dBm maximum		
	•802.11ax, MCS11(HT40): -59dBm maximum			
	•802.11ax, MCS11(VHT160): -58.5dBm maximum			
Antenna type	High efficiency an	tenna with spatial diversity, mounted in the display enclosure		
		Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN		
		tions and Bluetooth communications		
Form Factor		1iniCard with CNVi Interface		
Dimensions		1. Type 2230 : 2.3 x 22.0 x 30.0 mm		
		7 x 12.0 x 16.0 mm		
Weight	1. Type 2230 : 2.8g			
2. Type 126: 1.3g				
Operating Voltage		3.3v +/- 9%		
Temperature	Operating	14° to 158° F (–10° to 70° C)		
	Non-operating	–40° to 176° F (–40° to 80° C)		
Humidity	Operating	10% to 90% (non-condensing)		
	Non-operating	5% to 95% (non-condensing)		
Altitude	Operating	0 to 10,000 ft (3,048 m)		
	Non-operating	0 to 50,000 ft (15,240 m)		
LED Activity	LED Amber – Radi	LED Amber – Radio OFF; LED Off – Radio ON		
HP Integrated Module with Blue	etooth [®] 4.0/4.1/4.2/	5.0/5.1 Wireless Technology		
Bluetooth [®] Specification	4.0/4.1/4.2/5.0/5.	4.0/4.1/4.2/5.0/5.1 Compliant		
Frequency Band	2402 to 2480 MHz			
Number of Available Channels	Legacy : 0~79 (1 MHz/CH)			



	Legacy : Asynchronous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or 864 kbps symmetric (3-EV5)		
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum transmit power of +9.5 dBm for BR and EDR.		
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW Selective Suspend 17 mW		
Bluetooth® Software Supported Link Topology	Microsoft Windows Bluetooth® Software		
Power Management	Microsoft Windows ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249 ETS 300 328, ETS 300 826 Low Voltage Directive IEC60950 UL, CSA, and CE Mark		
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping LE Dual Mode LE Link Layer LE Low Duty Cycle Directed Advertising LE L2CAP Connection Oriented Channels Train Nudging & Interlaced Scan BT4.2 ESR08 Compliance LE Secure Connection- Basic/Full LE Privacy 1.2 –Link Layer Privacy LE Privacy 1.2 –Extended Scanner Filter Policies LE Data Packet Length Extension FAX Profile (FAX) Basic Imaging Profile (BIP)2 Headset Profile (HSP) Hands Free Profile (HFP) Advanced Audio Distribution Profile (A2DP)		

Realtek RTL8822CE 802.11ac 2x2 Wi-Fi + BT5			
Wireless LAN Standards	IEEE 802.11a		
	IEEE 802.11b		
	IEEE 802.11g		
	IEEE 802.11n		
	IEEE 802.11ac		
	IEEE 802.11d		
	IEEE 802.11e		
	IEEE 802.11h		
	IEEE 802.11i		
	IEEE 802.11k		
	IEEE 802.11r		
	IEEE 802.11v		
Interoperability	Wi-Fi [®] certified		
Frequency Band	802.11b/g/n		
	• 2.402 – 2.482 GHz		
	802.11a/n/ac		
	• 4.9 – 4.95 GHz (Japan)		
	• 5.15 – 5.25 GHz		
	• 5.25 – 5.35 GHz		
	• 5.47 – 5.725 GHz		
	• 5.825 – 5.850 GHz		



Data Rates	• 802.11b: 1, 2, 5.5, 11 Mbps		
	• 802.11g: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	• 802.11a: 6, 9, 12, 18, 24, 36, 48, 54 Mbps		
	 802.11n: MCS 0 ~ MCS 15, (20MHz, and 40MHz) 802.11ac : MCS0 ~ MCS9, (1SS, and 2SS) (20MHz, 40MHz & 80MHz) 		
Modulation	Direct Sequence Spread Spectrum		
	BPSK, QPSK, CCK, 16-QAM, 64-QAM, 256-QAM		
Security ³	• IEEE and WiFi compliant 64 / 128 bit WEP encryption for a/b/g mode only		
	AES-CCMP: 128 bit in hardware		
	802.1x authentication		
	 WPA, WPA2: 802.1x. WPA-PSK, WPA2-PSK, TKIP, and AES. WPA2 certification 		
	• IEEE 802.11i		
	• WAPI		
Network Architecture	Ad-hoc (Peer to Peer)		
Models	Infrastructure (Access Point Required)		
Roaming	IEEE 802.11 compliant roaming between access points		
Output Power ²	• 802.11b : +18.5dBm minimum		
	• 802.11g : +17.5dBm minimum		
	• 802.11a : +18.5dBm minimum		
	• 802.11n HT20(2.4GHz) : +15.5dBm minimum		
	• 802.11n HT40(2.4GHz) : +14.5dBm minimum		
	• 802.11n HT20(5GHz) : +15.5dBm minimum		
	• 802.11n HT40(5GHz) : +14.5dBm minimum		
	• 802.11ac VHT80(5GHz) : +11.5dBm minimum		
	• 802.11ac VHT160(5GHz) : +11.5dBm minimum		
Power Consumption	• Transmit mode :2.0 W		
	• Receive mode :1.6 W		
	• Idle mode (PSP) 180 mW (WLAN Associated)		
	 Idle mode :50 mW (WLAN unassociated) Connected Standby/Modern Standby: 10mW 		
	Radio disabled: 8 mW		
Power Management	ACPI and PCI Express compliant power management		
	802.11 compliant power saving mode		
Receiver Sensitivity ³	802.11b, 1Mbps : -93.5dBm maximum		
	802.11b, 11Mbps : -84dBm maximum		
	802.11a/g, 6Mbps : -86dBm maximum		
	802.11a/g, 54Mbps : -72dBm maximum		
	802.11n, MCS07 : -67dBm maximum		
	802.11n, MCS15 : -64dBm maximum		
	802.11ac, MCS0 : -84dBm maximum		
Antonna tupo	802.11ac, MCS9 : -59dBm maximum		
Antenna type	High efficiency antenna with spatial diversity, mounted in the display enclosure		
	Two embedded dual band 2.4/5 GHz antennas are provided to the card to support WLAN		
	MIMO communications and Bluetooth communications		
Form Factor	PCI-Express M.2 MiniCard with CNVi Interface		
Dimensions	1. Type 2230 : 2.3 x 22.0 x 30.0 mm		
Waight	2. Type 1216: 1.67 x 12.0 x 16.0 mm		
Weight	1. Type 2230 : 2.8g		
Operating Voltage	2. Type 126: 1.3g		
Operating Voltage	3.3v +/- 9%		
Temperature	Operating 14° to 158° F (–10° to 70° C)		
	Non-operating –40° to 176° F (–40° to 80° C)		



Humiditu	Operating	100/ to $000/$ (non condensing)		
Humidity	Operating Non-operating	10% to 90% (non-condensing) 5% to 95% (non-condensing)		
Altitude	Operating	0 to 10,000 ft (3,048 m)		
	Non-operating	0 to 50,000 ft (15,240 m)		
LED Activity	LED Amber – Rad			
	LED OFF – Radio OFF,			
HP Integrated Module with Bluet				
Bluetooth [®] Specification	4.0/4.1/4.2/5.0 Co			
Frequency Band	2402 to 2480 MHz	•		
Number of Available Channels				
Number of Available Chamilets	Legacy : 0~79 (1 MHz/CH) BLE : 0~39 (2 MHz/CH)			
Data Rates and Throughput	Legacy : 3 Mbps data rate; throughput up to 2.17 Mbps			
	BLE : 1 Mbps data	rate; throughput up to 0.2 Mbps		
	Legacy : Synchron	ous Connection Oriented links up to 3, 64 kbps, voice channels		
		nous Connection Less links 2178.1 kbps/177.1 kbps asymmetric (3-DH5) or		
	864 kbps symmetric (3-EV5)			
Transmit Power	The Bluetooth® component shall operate as a Class II Bluetooth® device with a maximum			
	transmit power of +4 dBm for BR and EDR.			
Power Consumption	Peak (Tx) 330 mW Peak (Rx) 230 mW			
	Selective Suspend 17 mW			
Bluetooth [®] Software Supported		s Bluetooth® Software		
Link Topology				
Power Management	Microsoft Window	s ACPI, and USB Bus Support		
Certifications	FCC (47 CFR) Part 15C, Section 15.247 & 15.249			
Power Management Certifications ETS 300 328, ETS 300 826		300 826		
i ower management eer tintations	Low Voltage Directive IEC950			
	UL, CSA, and CE Mark			
Bluetooth Profiles Supported	BT4.1-ESR 5/6/7 Compliance LE Link Layer Ping			
	LE Dual Mode			
	LE Link Layer			
		Directed Advertising		
	Train Nudging & In	ion Oriented Channels		
	BT4.2 ESR08 Com			
	LE Secure Connect			
	LE Privacy 1.2 –Link Layer Privacy			
	LE Privacy 1.2 –Extended Scanner Filter Policies			
	LE Data Packet Lei	ngth Extension		
	FAX Profile (FAX)			
	Basic Imaging Prof			
	Headset Profile (H Hands Free Profile	-		
		istribution Profile (A2DP)		



Technical Specifications – Input/Output Devices

I/O DEVICES

HP Wired Desktop 320K K	eyboard	
Physical Characteristics	Keys	104, 105, 107, 109 layout (depending on country)
	Dimensions (L x W x H)	16.77 x 4.36 x 0.65 in (426.2 x 110.9 x 16.7 mm)
	Weight	14.57 oz (413g)
	Cable length	6 ft. (1.8 m)
Electrical	Operating voltage	5V
	Power consumption	50mA - 100 mA
	System interface	USB
Mechanical	Кеусарѕ	Low-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback
	Switch life	10 million keystrokes (Life tester)
	Switch type	Plunger
Environmental		
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 149° F (-30° to 65° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	0% to 90% (non-condensing at ambient)
Approvals	FCC, ICES, CULus, CE, GS, EAC, Ukraine, India BIS, KCC, RCM, BSMI, VCCI	
Ergonomic compliance	TUVGS	
Kit contents	Keyboard, QSP, Warranty Card	, Product Notice

HP USB Premium Keyboard	d	
Physical Characteristics	Keys	104, 105 layout (depending upon country)
	Dimensions (L x W x H)	17.04 x 5.55 x 0.52 in (433 x 141 x13.2 mm)
	Weight	1.54 lb. (698g)
	Operating voltage	5 VDC, +/-5%
	Power consumption	35mA (All LED on)
Flactrical	System interface	USB Type A plug connector
Electrical	ESD	Contact Discharge: 8 KV Air Discharge: 15 KV
	EMI - RFI	Conforms to FCC rules for a Class B computing device
	Microsoft [®] PC 99 - 2001	Functionally compliant
Mechanical	Кеусарѕ	Low-profile design
	Switch actuation	60±10g nominal peak force with tactile feedback



Technical Specifications – Input/Output Devices

	Switch life	10 million keystrokes (Life tester)
	Switch type	Contamination-resistant switch membrane
	Key-leveling mechanisms	For all double-wide and greater-length keys
	Cable length	6 ft. (1.8 m)
	Microsoft PC 99 - 2001	Mechanically compliant
	Acoustics	43-dBA maximum sound pressure level
	Operating temperature	50° to 122° F (10° to 50° C)
	Non-operating temperature	-22° to 140° F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
Environmental	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	40 g, six surfaces
	Non-operating shock	80 g, six surfaces
	Operating vibration	2-g peak acceleration
	Non-operating vibration	4-g peak acceleration
	Drop (out of box)	26 in (66 cm) on carpet, six-drop sequence
	Drop (in box)	30 in (76.2 cm) on concrete, 16-drop sequence
Approvals	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC	
Ergonomic compliance	TUVGS	
Kit contents	Keyboard, QSP	
Warranty Card	Product Notice	

HP Wired Desktop 320M	Mouse	
Dimensions (H x L x W)	4.08 x 2.49 x 1.39 in (103.8 x 63.4 x 35.5 mm)	
Weight	2.67 oz (75.8 g)	
Mechanical	Connector	USB
	Resolution	1000 DPI
	Sensor	Optical Red Sensor
Tracking speed	Tracking acceleration	8G(max), 1G=9.8m/s2
	Cable length	6 ft. (1.8 m)
	Color	Jack Black
Regulatory approvals	Compliant	FCC, ICES, CULus, CE, GS, EAC, Ukraine. India BIS, KCC, RCM, BSMI, VCCI



Technical Specifications – Input/Output Devices

HP USB Premium Mouse		
Dimensions (H x L x W)	4.21 x 2.64 x 1.52 in (107 x 67 x	x 38.7 mmm)
Weight	0.19lb (90g)	
Environmental	Operating temperature	50° to 122°F (10° to 50° C)
	Non-operating temperature	-22° to 140°F (-30° to 60° C)
	Operating humidity	10% to 90% (non-condensing at ambient)
	Non-operating humidity	20% to 80% (non-condensing at ambient)
	Operating shock	50 g, 6 surfaces
	Non-operating shock	80 g, 6 surfaces
	Operating vibration	2 g peak acceleration
	Non-operating vibration	4 g peak acceleration
Electrical	Operating voltage	5 VDC, +/-5%
	Power consumption	12mA
Mechanical	Connector	USB 2.0
	Туре	3D mouse (3 keys and wheel)
	Resolution	800, 1200, 1600 DPI
	Sensor	Pixart PAN3606DL
Tracking speed	Tracking acceleration	8G(max), 1G=9.8m/s2
	Cable length	6 ft. (1.8 m)
	Color	Jack Black
Regulatory approvals	Compliant	UL, FCC, CE Mark, TUV GS, VCCI, BSMI, RCM, KCC

HP USB Mouse			
Dimensions (H x L x W)	37mm x 115mm x 62.	37mm x 115mm x 62.9mm	
Weight	90 +10g/- 5 g	90 +10g/- 5 g	
Color	Black	Black	
Connector	USB	USB	
	Resolution	800 DPI sensitivity	
Mechanical	Buttons	Two primary buttons and clickable scroll wheel	

Technical Specifications – Audio/Multimeda

AUDIO/MULTIMEDIA

HP EliteDesk 800 G6 Tower Business PC

Туре	Integrated
HD Stereo Codec	Conexant CX20632
Audio I/O Ports	Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line- out, Microphone-in or Headphone-out port 1 - Headphone port Rear: 1 - Line-out 1 - Line-in which is retaskable as a Microphone Input All ports are 3.5mm and support stereo
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes – Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes

HP EliteDesk 800 G6 Small Form Factor Business PC

Туре	Integrated
HD Stereo Codec	Conexant CX20632
Audio I/O Ports	Front: 1 - Headset connector supports a CTIA style headset and is re-taskable as a Line-in, Line- out, Microphone-in or Headphone-out port 1 - Headphone port Rear: 1 - Line-out 1 - Line-in which is retaskable as a Microphone Input All ports are 3.5mm and support stereo
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes



Technical Specifications – Audio/Multimeda

HP EliteDesk 800 G6 Desktop Mini Business PC

Туре	Integrated
HD Stereo Codec	Realtek ALC3205-CG
Audio I/O Ports	combo audio jack with CTIA and OMTP headset support
Internal Speaker Amplifier	2W class D mono amplifier for the internal speaker only. External speakers must be powered
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speaker.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes

HP EliteOne 800 G6 24 & 27 All-in-One

Bang & Olufsen Audio	
Туре	Integrated
HD Stereo Codec	Realtek ALC3274
	Side headset connector supports a CTIA/OMTP style headset and is re-taskable as a Line-in, Line- out, Microphone-in or Headphone-out port Side headphone connector supports a headphone connections Rear line out connector
Audio I/O Ports	All ports are 3.5mm and support stereo
Internal Speaker Amplifier	5W per channel class D stereo amplifier for the internal speakers only
Multi-streaming Capable	Playback multi-streaming can be enabled in the audio control panel to allow independent audio streams to be sent to/from the front and rear jacks or integrated speakers.
Sampling	Independent sampling rates for DAC's and ADC's; supports resolutions from 16 to 24-bit; 44.1 kHz to 192 kHz for DAC and 44.1 kHz to 96 kHz for ADC
Wavetable Syntheses	Yes - Uses OS soft wavetable
Analog Audio	Yes
# of Channels on Line-Out	Stereo (Left & Right channels)
Internal Speaker	Yes - Stereo



Technical Specifications – Integrated Webcam and Microphone

INTEGRATED WEBCAM AND MICROPHONE

Integrated Webcam and Microphone

Optional integrated 5 MP Full HD RGB webcam & microphone; maximum resolution of 2624 x 1976 Optional integrated 5 MP Full HD RGB dual-facing webcam with IR sensor (user-facing) & microphone; maximum resolution of 2624 x 1976

NOTE: All HP devices which carry the Bang & Olufsen brand are custom-tuned with Bang & Olufsen's acoustical engineers for precise sound experience in business use.

INTEGRATED FINGERPRINT SENSOR

Sensor type: Touch Fingerprint matching: Performed on device Anti-Spoofing: Yes Windows Hello Support: Yes Encryption: On sensor FIPS Compliant: No



Technical Specifications – Power

POWER

HP EliteDesk 800 G6 Tower Business PC

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~35°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G6 SFF Business PC

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~35°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G6 Desktop Mini Business PC (35W)

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~35°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G6 Desktop Mini Business PC (65W)

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~35°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)

HP EliteDesk 800 G6 Desktop Mini Business PC (95W)

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~35°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)



Technical Specifications – Power

HP EliteOne 800 G6 24 & 27 All-in-One

Unit Environment and Operating Conditions

Temperature Range	Operating: 5°C ~45°C Non-Operating: -40°C ~66°C
Relative Humidity	Operating 5% to 90% relative humidity at max inlet temperature Non-Operating 5% to 90% relative humidity at max inlet temperature
Maximum Altitude (unpressurized)	Operating: 5000m Non-operating: 50,000 ft. (15240 m)

	DM	SFF	TWR	AiO
External Power Supplies	65W EPS, 88% average efficiency at 115V & 89% at 230Vac 90W EPS, active PFC, 88% average efficiency at 115V & 89% at 230Vac 150W EPS, active PFC, 88% average efficiency at 115V & 89% at 230Vac	N/A	N/A	N/A
80 PLUS Gold	N/A	N/A	N/A	N/A
80 PLUS Platinum	N/A	350W active PFC / 80 PLUS Platinum 260W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	550W active PFC / 80 PLUS Platinum 350W active PFC / 80 PLUS Platinum 260W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)	210W active PFC / 80 PLUS Platinum 280W active PFC / 80 PLUS Platinum 90/92/89% efficient at 20/50/100% load (115V) 91/93/90% efficient at 20/50/100% load (230V)
Operating Voltage Range	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac	90Vac~264Vac
Rated Voltage Range	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac	100Vac~240Vac
Rated Line Frequency	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ	50HZ~60HZ
	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ	47HZ~63HZ
Rated Input Current				
Rated Input Current with Energy Efficient* Power Supply	65W≦1.6A 90W≦1.2A 150W≦2.2A	260W Platinum≦3.1A 350W Platinum≦4A	260W Platinum \leq 3.1A 350W Platinum \leq 4A 550W Platinum \leq 6.6A	210W ≦2.8A 280W≦3.2A
DC Output	+19.5V	+12V	+12V	+12V



Technical Specifications – Power

	DM	SFF	TWR	AiO
Current Leakage (NFPA 99:	Less than 500	Less than 500	Less than 500	Less than 500
Current Leakage (NFPA 99: 2102)	microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances	microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances	microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non-patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-patient Electrical Appliances	microamps of leakage current at 120 Vac with the ground wire disconnected, as required for Non- patient Electrical Appliances and Equipment used in a patient care facility or that contact patients in normal use. Per section 10.3.5.1. Less than 100 microamps of leakage current at 120 Vac with the ground wire intact with normal polarity, as required for Non-
		and Equipment used in a patient care facility or that contact patients in	and Equipment used in a patient care facility or that contact patients in	
Power Supply Fan	N/A	70mm variable speed	70mm variable speed	N/A
Power cord length	6.0 ft. (1.83 m)	· · ·	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)
External Power Adapter	External power supply	Internal power supply	Internal power supply	Internal power supply
Dimensions	65W: 113.5mm x 55mm x 30mm 90W: 132mm x 57mm x 30mm 150W: 160mm x 80mm x 40mm	165mm x 95mm x	165mm x 95mm x 73mm	110x110x26mm
Total Cord Length	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)	6.0 ft. (1.83 m)

QuickSpecs

Technical Specifications – Power

The power supply shall comply with harmonic input current requirements as detailed in EN61000-3-2 and JEIDA MITI standards. The harmonic input current requirements must be met under the following operating conditions: Load Requirements: 50% and 100%

Input Voltage: 230Vac/50Hz.

For active power factor correction the power factor at 50% &100% loads shall be greater than 0.9 over the entire nominal input voltage range (100-127VAC and 200-240VAC).

Condition	Standard Efficiency	82/85/82%	85/88/85%	87/90/87%	90/92/89%	Input Voltage
10% of Rated Load	-	75%	81%	84%	86%	115Vac/60HZ
20% of Rated Load	-	82%	85%	87%	90%	115Vac/60HZ
50% of Rated	-	85%	88%	90%	92%	115Vac/60HZ
Load	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.95	
100% of Rated	70%	82%	85%	87%	89%	115Vac/60HZ
Load	PF>0.9	PF>0.9	PF>0.9	PF>0.9	PF>0.9	230Vac/50HZ



WEIGHTS & DIMENSIONS

	DM	SFF	TWR	AiO
Chassis (W x D x H)	6.97 x 6.89 x 1.35 in 177 x 175 x 34 mm	13.3 x 12.13 x 3.94 in 338 x 308 x 100 mm	14.57 x 12.13 x 6.61 in 370 x 308 x 168 mm	See table below.
System Volume	63.4 cu in 1.05L	634.6 cu in 10.4 L	1186.8 cu in 19.14 L	See table below.
System Weight	3.13 lb 1.42 kg	13.5 lb 6.13 kg	21.74 lb 9.86 kg	See table below.
Max Supported Weight (desktop orientation)	: 0	77 lb 35 kg	77 lb 35 kg	See table below.
Stand Dimensions	160 x 117 x 18.5 mm	151.8 x 200 x 37.2mm	N/A	See table below.
Packaging (W x D x H)	19.6 x 5.2 x 9.3 in 498 x132 x 235 mm	15.71 x 19.65 x 9.06 in 399 x 499 x 230 mm	11.77 x 18.82 x 20.35 in 299 x 478 x 517 mm	See table below.
Shipping Weight	2.95 kg 6.49 lb	9 kg 19.82 lb	11.34 kg 24.98 lb	See table below.
Multipack Packaging (10 units)	20.28 x16.54 x 25 in 515 x 420 x 636 mm			
Palletization Profile	10-units per layer 10 layers max 100 units per pallet 46.3 x 39.2 x 57.7 in, 1175 x 996 x 2125 mm (include pallet)	6 units per layer 10 layers max 60 units per pallet 1200 x 1000 x 2438 mm (include the pallet)	8 units per layer 4 layers ax 32 units per pallet 1200 x 1000 x 2203 mm (include the pallet)	10-units per layer 4-layers max 40-units per pallet (sea) 1200 x 1000 x 2470 mm



176.84mm

000000

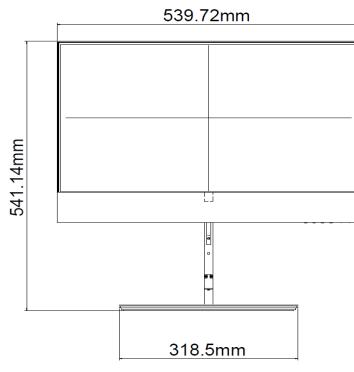
1

л

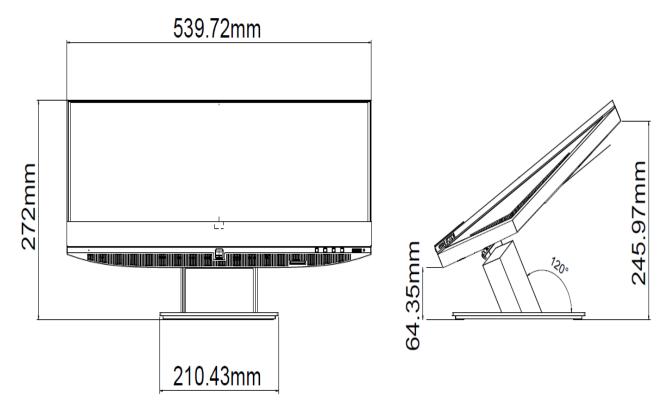
Technical Specifications – Weights and Dimensions

STANDS AND DIMENSIONS

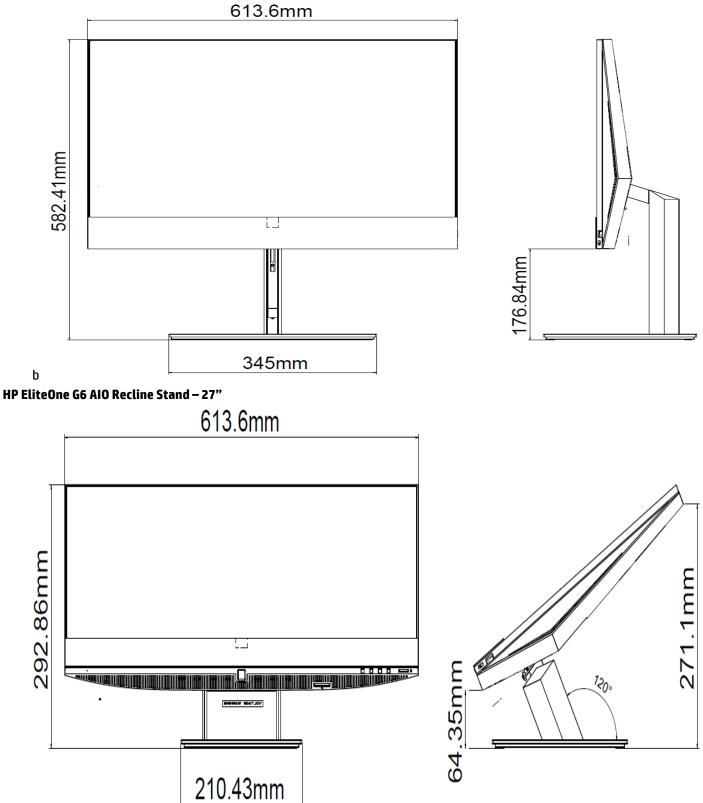
HP EliteOne G6 AIO Adjustable Height Stand – 23.8"







HP EliteOne G6 AIO Adjustable Height Stand – 27"





Adjustable Height Stand:	Height - Vertical/Landscape Adjustment	130mm (±2 mm)	
	Portrait Adjustment	No portrait	
	Tilt Angle	-5° to +18° (±2°) in landscape and portrait	
	Rotation (Swivel)	90° (±1°) (45 left, 45 right)	
	Pivot	No pivot	

Recline Stand:	Height - Vertical Adjustment	No height
	Tilt Angle	+36.5° to +58° (+/-1.5°)
	Rotation (swivel)	No swivel



ALL-IN-ONE WEIGHTS AND DIMENSIONS

Weight without Touch Panel – 23.8"

Product Weight Unboxed	Without Stand 15.12 lbs. 6.86 kg	Adjustable Height Stand 20.46 lbs. 9.28 kg	Recline Stand 18.83 lbs. 8.54 Kg
Shipping Weight Boxed	Without Stand 19.51 lbs. 8.85 kg	Adjustable Height Stand 24.85 lbs. 11.27 kg	Recline Stand 23.08 lbs. 10.47 kg
Shipping Weight Pallet (30 units)	Without Stand 623.7 lbs. 283.5 kg	Adjustable Height Stand 783.4 lbs. 356.1 kg	Recline Stand 730.62 lbs. 332.1 kg

Weight with Touch Panel – 23.8"

Product Weight Unboxed	Without Stand 17.50 lbs. 7.94 kg	Adjustable Height Stand 22.84 lbs. 10.36 kg	Recline Stand 21.21 lbs. 9.62 Kg
Shipping Weight Boxed	Without Stand 21.89 lbs. 9.93 kg	Adjustable Height Stand 27.23 lbs. 12.35kg	Recline Stand 25.46 lbs. 11.55 kg
Shipping Weight Pallet (30 units)	Without Stand 694.98 lbs. 315.9 kg	Adjustable Height Stand 854.7lbs. 388.5kg	Recline Stand 801.9lbs. 364.5 kg

Dimensions (W x D x H) – 23.8"

Product Dimensions (Non-touch)	Without Stand 539.72 x 364.3 x 57.3 mm	Stand (-5 ~ 20) degrees	Recline Stand Stand (30 ~ 60) degrees 539.72 x 379.44 x 209.35 mm
Product Dimensions (Sure View/ In-cell Touch)	Without Stand 539.72 x 364.3 x 59.3 mm	Stand (-5 ~ 20) degrees	Recline Stand Stand (30 ~ 60) degrees 539.72 x 379.44 x 211.35 mm

Shipping Dimensions – 23.8"

		 Recline Stand 628 x 186 x 635 mm
Shipping Dimensions Pallet Pallet (40 units)	Without Stand 1180 x 874 x 2060 mm	 Recline Stand 1180 x 874 x 2060 mm



Weight with Touch Panel – 27"

Product Weight Unboxed	VeightWithout StandAdjustable Height19.56 lbs.Stand8.87 kg25.40 lbs.11.52 kg		Recline Stand 23.26 lbs. 10.55 Kg		
Shipping Weight Boxed	Without Stand 25.46 lbs. 11.55 kg	Adjustable Height Stand 31.31 lbs. 14.2 kg	Recline Stand 29.17 lbs. 13.23 kg		
Shipping Weight Pallet (18 units)			Recline Stand 563.5 lbs. 256.14 kg		

Weight without Touch Panel – 27"

Product Weight Unboxed	Without Stand 17.79 lbs. 8.07 kg	Adjustable HeightRecline StandStand21.50 lbs.23.63 lbs.9.75 Kg10.72 kg		
Shipping Weight Boxed	Without Stand 23.70 lbs. 10.75 kg	Adjustable Height Stand 29.54 lbs. 13.4 kg	Recline Stand 27.40 lbs. 12.43 kg	
Shipping Weight Pallet (18 units)	Without Stand 465.3 lbs. 211.5 kg	Adjustable Height Stand 570.24 lbs. 259.2 kg	Recline Stand 531.83 lbs. 241.74 kg	

Dimensions (W x D x H) - 27"

613.6 x 405.57 x 58.7 mm	Stand (-5 ~ 20) degrees	Recline Stand Stand (30 ~ 60) degrees 613.6 x 420.71 x 210.68 mm
 613.6 x 405.57 x 59.07 mm	Stand (-5 ~ 20) degrees	Recline Stand Stand (30 ~ 60) degrees 613.6 x 420.71 x 211.05 mm

Shipping Dimensions – 27"

	742 x 237 x 640 mm	 Recline Stand 742 x 237 x 640 mm
Shipping Dimensions Pallet Pallet (18 units)		 Recline Stand 1180 x 958 x 2076 mm



Technical Specifications – Miscellaneous Features

MISCELLANEOUS FEATURES

Management Features

- Advanced Configuration and Power Management Interface (ACPI). Allows the system to wake from a low power mode. Controls system power consumption, making it possible to place individual cards and peripherals in a low-power or powered-off state without affecting other elements of the system.
- Intel[®] Wired for Management support; industry wide initiative to make Intel[®] architecture based PCs, servers and mobile computers more inherently manageable out-of-the-box and over the network
- Dual State Power Button; acts as both an on/off button and a suspend-to-sleep button

Serviceability Features

- Dual colored power LED on front of computer to indicate either normal or fault condition
- Diagnostic LED Explanation Table:
 - Power LED will blink red 2 to 5 times, then blink white 2 or more times, then repeat (with beep tones for each blink initially):
 - 2 red + 2 white User must provide file for BIOS recovery (USB storage typically)
 - 2 red + 3 white User must enter a key sequence to proceed with recovery by policy
 - 2 red + 4 white BIOS recovery is in progress
 - 3 red + 2 white Memory could not be initialized
 - 3 red + 3 white Graphics adaptor could not be found
 - 3 red + 4 white Power supply failure / not connected
 - 3 red + 5 white Processor not installed
 - 3 red + 6 white Current processor does not support an enabled feature
 - 4 red + 2 white Processor has exceeded its temperature threshold / system thermal shutdown
 - 4 red + 3 white System internal temperature has exceeded its threshold
 - 5 red + 2 white System controller firmware is not valid
 - 5 red + 3 white System controller detected BIOS is not executing
 - 5 red + 4 white BIOS could not complete initialization / PCA failure
 - 5 red + 5 white System controller rebooted the system after a health or recovery timer triggered
- HP PC Hardware Diagnostics UEFI:

.

- This utility enables hardware level testing outside the operating system on many components. The diagnostics can be invoked by pressing F2 at POST, and is available as a download from HP Support
- System/Emergency ROM
- Flash ROM
- CMOS Battery Holder for easy replacement
- Flash Recovery with Video Configuration Record Software5 Aux Power LED on System PCA
- Processor ZIF Socket for easy Upgrade
- Over-Temp Warning on Screen (Requires IM Agents)
- DIMM Connectors for easy Upgrade
- Clear CMOS Button
- NIC LEDs (integrated) (Green & Amber)
- Dual Color Power and HD LED To Indicate Normal Operations and Fault Conditions
- Color coordinated cables and connectors
- Tool-less Hood Removal
- Front power switch
- System memory can be upgraded without removing the system board or any internal components
- Tool-less Hard Drive, CD & Diskette Removal (For MT, SFF, and DM only)
- Green Pull Tabs, and Quick Release Latches for easy Identification

Technical Specifications – Miscellaneous Features

Additional Features	Description
Tower Orientation	Product can be oriented as either a desktop (horizontal) or a tower (vertical) for MT, SFF, and DM only. SFF/DM requires optional stand.
Drive Lock	Implementation of the industry standard ATA Security feature set. When enabled, it prevents software access to user data on the drive until one or two user-defined passwords are provided.
Boot Sectors Protection	MBR and GPT sectors of the hard drive are critical to booting the operating system. By saving the MBR or GPT data (depending on the how the OS was installed), the BIOS will be able to monitor for changes and allow the user to override them with the backup copy at boot-up.
Drive Protection System	DPS Access through F10 Setup during Boot (for SATA hard drive only)
	A diagnostic hard drive self- test. It scans critical physical components and every sector of the hard drive for physical faults and then reports any faults to the user
	Running independently of the operating system, it can be accessed through a Windows-based diagnostics utility or through the computer's setup procedure. It produces an evaluation on whether the hard drive is the source of the problem and needs to be replaced
	The system expands on the Self-Monitoring, Analysis, and Reporting Technology (SMART), a continuously running systems diagnostic that alerts the user to certain types of failures
SMART Technology (Self-Monitoring, Analysis and Reporting Technology)	Allows hard drives to monitor their own health and to raise flags if imminent failures were predicted
SMART I - Drive Failure Prediction	Predicts failures before they occur. Tracks fault prediction and failure indication parameters such as re-allocated sector count, spin retry count, calibration retry count
SMART II - Off-Line Data Collection	By avoiding actual hard drive failures, SMART hard drives act as "insurance" against unplanned user downtime and potential data loss from hard drive failure
SMART III - Off-Line Read Scanning with Defect Reallocation	IOEDC: I/O Error Detection Circuitry
SMADT IV End to End CDC for bard drives	Detects errors in Read/Write buffers on HDD sache RAM

SMART IV - End-to-End CRC for hard drives Detects errors in Read/Write buffers on HDD cache RAM



Technical Specifications – After Market Options

AFTER MARKET OPTIONS

Graphics Solutions	DM	<u>SFF</u>	TWR	<u>Ai0</u>	Part Number
AMD® Radeon™ RX 550X 4GB Display Port Card		X			5LH79AA
AMD® Radeon™ R7 430 2GB 2 Display Port Card		X	X		5JW82AA
AMD [®] Radeon™ R7 430 2GB DP+VGA Card		X	X		5JW81AA

Desktop Mini Accessories	DM	<u>SFF</u>	MT	<u>Ai0</u>	<u>Part Number</u>
HP Desktop Mini Port Cover v3	<u>X</u> (95W and discrete GPU skus not supported)				13L69AA
HP Desktop Mini 2.5" SATA Drive Bay kit v2	<u>X</u> (95W and discrete GPU skus not supported)				13L70AA
HP Desktop Mini 65W Power Supply Kit	<u>X</u>				L2X04AA
HP Desktop Mini 90W Power Supply Kit	<u>X</u>				L4R65AA
HP Desktop Mini LockBox V2	<u>X</u> (95W and discrete GPU skus not supported)				3EJ57AA
HP Desktop Mini DVD-Writer ODD Expansion Module	V (Fither and)				K9Q83AA
HP Desktop Mini I/O Expansion Module	<u>X (Either one)</u>				K9Q84AA
HP Desktop Mini Security/Dual VESA Sleeve v3	<u>X</u> (95W and discrete GPU skus not supported)				13L67AA
HP Desktop Mini Security/Dual VESA Sleeve v3 with Power Supply Holder	<u>X</u> (95W and discrete GPU skus not supported)				13L68AA
HP B250 PC Mounting Bracket	<u>X</u>				<u>8RA46AA</u>
HP B300 PC Mounting Bracket	<u>X</u>				<u>2DW53AA</u>
HP B300 PC Mounting Bracket with Power Supply Holder	<u>X</u> (95W and discrete GPU skus not supported)				<u>7DB37AA</u>
HP B500 PC Mounting Bracket	<u>X</u>				<u>2DW52AA</u>
HP Desktop Mini Vertical Chassis Stand	<u>X</u>				<u>G1K23AA</u>
HP DM Power Supply Holder Kit v2	<u>X</u> (95W and discrete GPU skus not supported)				<u>7DB38AA</u>
HP Quick Release Bracket 2	<u>×</u>			<u>X</u> (required pre- configured VESA <u>adapter</u>	<u>6KD15AA</u>
HP Single Monitor Arm	<u>X</u>			<u>X</u>	<u>BT861AA</u>

QuickSpecs

Technical Specifications – After Market Options

Data Storage Drives	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>Ai0</u>	<u>Part Number</u>
HP PCIe NVME TLC 256GB SSD M.2 Drive	X	X	X	X	1CA51AA
HP PCIe NVME TLC 512GB SSD M.2 Drive	X	X	X	X	X8U75AA
HP 500GB 7200PRM SATA 3.5" Hard Drive		X	X		QK554AA
HP 1TB 7200rpm SATA 3.5" Hard Drive		X	X		QK555AA
HP 9.5mm Tower DVD-Writer		X	X		1CA52AA

Input Devices	DM	<u>SFF</u>	TWR	AiO	<u>Part</u> <u>Number</u>
HP Desktop Wired 320K Keyboard	X	X	X	X	9SR37AA
HP Desktop Wired 320M Mouse	X	X	X	X	9VA80AA
HP Desktop Wired 320MK Mouse and Keyboard	X	X	X	X	9SR36AA
HP USB Antimicrobial Business Slim Keyboard and Mouse	X	X	X	X	Z9H50AA
HP USB Business Slim CCID SmartCard Keyboard	X	X	X	X	Z9H48AA
HP USB Keyboard	X	X	X	X	QY776AA
HP USB Keyboard and Mouse Healthcare Edition	X	X	X	X	1VD81AA
HP USB Premium Keyboard	X	X	X	X	Z9N40AA
HP USB PS/2 Washable Keyboard & Mouse	X	X	X	X	BU207AA
HP Wireless Business Slim Keyboard and Mouse	X	X	X	X	N3R88AA
HP Wireless Premium Keyboard	X	X	X	X	Z9N41AA
HP PS/2 Business Slim Keyboard		X	X		N3R86AA
HP USB Fingerprint Mouse	X	X	X	X	4TS44AA
HP USB Premium Mouse	X	X	X	X	1JR32AA
HP PS/2 Mouse		X	X		QY775AA
HP Wireless Premium Mouse	X	X	X	X	1JR31AA
HP USB 1000dpi Laser Mouse	X	X	X	X	QY778AA
HP USB Optical Mouse	X	X	X	X	QY777AA
HP USB Hardened Mouse ¹	X	X	X	X	P1N77AA

1. Not available in all regions

System Memory	DM	<u>SFF</u>	TWR	<u>AiO</u>	<u>Part</u>
					<u>Number</u>
HP 4GB DDR4-2666 DIMM		X	X		3TK85AA
HP 8GB DDR4-2666 DIMM		X	X		3TK87AA
HP 16GB DDR4-2666 DIMM		X	X		3TK83AA
HP 32GB DDR4-2666 DIMM		X	X		1C918AA
HP 4GB DDR4-2666 SODIMM	X			X	3TK86AA
HP 8GB DDR4-2666 SODIMM	X			X	3TK88AA
HP 16GB DDR4-2666 SODIMM	X			X	3TK84AA
HP 32GB DDR4-2666 SODIMM	X			X	1C919AA
HP 4GB DDR4-3200 UDIMM		X	X		13L78AA



QuickSpecs

Technical Specifications – After Market Options

HP 8GB DDR4-3200 UDIMM		X	X		13L76AA
HP 16GB DDR4-3200 UDIMM		X	Х		13L74AA
HP 32GB DDR4-3200 UDIMM		X	Х		13L72AA
HP 4GB DDR4-3200 SODIMM	X			X	13L79AA
HP 8GB DDR4-3200 SODIMM	X			X	13L77AA
HP 16GB DDR4-3200 SODIMM	X			X	13L75AA
HP 32GB DDR4-3200 SODIMM	X			X	13L73AA

Multimedia Devices	DM	<u>SFF</u>	<u>TWR</u>	<u>Ai0</u>	<u>Part Number</u>
HP Business Headset v2	X	X	X	X	T4E61AA
HP S101 Speaker Bar	X	X	X		5UU40AA
HP UC Speaker Phone v2	X	X	X		4VW02AA

Security Devices	<u>DM</u>	<u>SFF</u>	<u>TWR</u>	<u>Ai0</u>	<u>Part</u> <u>Number</u>
HP Business PC Security Lock v3 Kit		X	Х		3XJ17AA
HP Dual Head Keyed Cable Lock		X	X		T1A64AA
HP Keyed Cable Lock 10mm	X	X	X	Х	T1A62AA
HP Master Keyed Cable Lock 10mm	X	X	X	Х	T1A63AA
HP Sure Key Cable lock	X				6UW42AA

Stands and Accessories	DM	<u>SFF</u>	TWR	<u>Ai0</u>	<u>Part Number</u>
HP EliteOne 800 G6 23.8" Height Adjustable Stand				x	13L61AA
HP EliteOne 800 G6 23.8" Recline Stand				X	13L62AA
HP EliteOne 800 G6 27" Height Adjustable Stand				x	13L63AA
HP EliteOne 800 G6 27" Recline Stand				X	13L64AA

I/O Devices	DM	<u>SFF</u>	<u>TWR</u>	<u>Ai0</u>	<u>Part Number</u>
HP DisplayPort Port Flex IO v2	X	X	X		13L54AA
HP HDMI Port Flex IO v2	X	X	X		13L55AA
HP Type-C [®] USB 3.1 Gen2 Port Flex IO v2	X	X	X		<u>13L59AA</u>
HP Type-C [®] USB 3.1 Gen2 Port with PD Flex IO v2	X (Not Available on 95W and discrete GPU SKUs)				<u>13L60AA</u>
HP USB 3.1 Gen1 x2 Module Flex IO v2	X (Not Available on 95W and discrete GPU SKUs)	х	x		13L58AA
HP VGA Port Flex IO v2	X	X	X		<u>13L53AA</u>
HP Serial Port Flex IO v2	X (Not Available on 95W and discrete GPU SKUs)	x	x		<u>13L56AA</u>



Technical Specifications – After Market Options

HP Serial Port Flex IO 2 v2	X (Not Available on 95W and discrete GPU SKUs)			<u>13L57AA</u>
HP Internal Serial Port (in rear wall)		X	X	3TK82AA
HP PCIe x1 Parallel Port Card		X	X	N1M40AA
HP Serial/PS/2 Adapter Kit (in PCIe slot)		X	X	1VD82AA
HP USB to Serial Port Adapter	X	X	X	J7B60AA
HP USB-C to Display Port Adapter	X	X	X	N9K78AA
HP Single Mini Display Port Adapter to Display Port Adapter	X (Only Available with GPU SKUs)			2MY05AA

NOTE: For more detail on HP I/O Devices please refer to the HP FLEX IO Option Cards QuickSpecs. URL is: http://h20195.www2.hp.com/v2/GetDocument.aspx?docname=c06042607

Communication Devices	<u>DM</u>	<u>SFF</u>	TWR	<u>Ai0</u>	<u>Part Number</u>
Intel [®] Ethernet I210-T1 GbE NIC		X	X		<u>E0X95AA</u>

Intel® Optane Memory	DM	<u>SFF</u>	<u>TWR</u>	<u>Ai0</u>	<u>Part Number</u>
Intel® Optane Memory 16GB (Cache)	X	X	X		1WV97AA
512GB Intel® Optane™ Memory H10 with SSD	x	X	X	х	6VF55AA

Change Log

© Copyright 2021 HP Development Company, L.P.

The information contained herein is subject to change without notice. The only warranties for HP products are set forth in the express limited warranty statements accompanying such products. Nothing herein should be construed as constituting an additional warranty. HP shall not be liable for technical or editorial errors or omissions contained herein. Microsoft and Windows are registered trademarks or trademarks of Microsoft Corporation in the U.S. and/or other countries. Intel, Celeron, Core, Pentium are registered trademarks or trademarks of Intel Corporation in the U.S. and/or other countries. Bluetooth[®] is a trademark of its proprietor, used by HP, Inc. under license. USB Type-C[®] and USB-C[®] are trademarks of USB Implementers Forum. NVIDIA, GeForce and NVS are trademarks and/or registered trademarks of NVIDIA Corporation in the U.S. and other countries. AMD and Radeon are trademarks of Advanced Micro Devices, Inc. ENERGY STAR is a registered trademark owned by the U.S. Environmental Protection Agency. DisplayPort[™] and the DisplayPort[™] logo are trademarks owned by the Video Electronics Standards Association (VESA[®]) in the United States and other countries.

Date	Version History	Action	Description of Change
July 15, 2020	From v1 to v2	Addition	Supported versions section
July 22, 2020	From v2 to v3	Addition	NVIDIA [®] GeForce [®] RTX 2070 Super 8GB GDDR6
August, 2020	From v3 to v4	Addition	DVD-R DL - Up to 6X, DVD+R DL - Up to 6X, DVD-R SL/DL Up to 8X and DVD+R SL/DL Up to 8X on the read/write speed on the blue ray write drive specs on Storage section. Specs for DM environmental section completed. DM rear call outs corrected.
October 6, 2020	From v4 to v5	Correction	ALL-IN-ONE WEIGHTS AND DIMENSIONS tables information.
October 7, 2020	From v5 to v6	Addition	Environmental specs for SFF
October 8, 2020	From v6 to v7	Update	Environmental specs for AiO 24
October 8, 2020	From v6 to v7	Update	Environmental specs for AiO 24
October 27, 2020	From v8 to v9	Correction	Processors footnotes and Turbo boost specs corrected
November 13, 2020	From v9 to v10	Addition	Specification at External Power Supplies row in POWER section
November 20, 2020	From v10 to v11	Correction	Rear components and rear ports call outs section and NVIDIA® GeForce® RTX 2070 Super 8GB GDDR6 specs corrected
November 26, 2020	From v11 to v12	Addition	Environmental specs for TWR
January 6, 2021	From v12 to v13	Update/add	Footnotes added to "At a glance" section and packaging materials data in 23.8-in All-in-One Environmental info updated
January 20, 2021	From v13 to v14	Correction	Intel® i210 10/100/1000 NIC in N&C section corrected
January 21, 2021	From v14 to V15	Removal	HP Thunderbolt 3.0 (4CX35AA) from AMO section
January 26, 2021	From v15 to v16	Correction	System volume for TWR and SFF in Weights and dimensions section
February 17, 2021	From v16 to v17	Correction	"Anti-glare" removed from 27.0" LCD (2560 x 1440) Touch in DISPLAY PANEL SPECIFICATIONS
February 24, 2021	From v17 to v18	Update	At a Glance section Raid bullet and Fiber NIC specification added
March 22, 2021	From v18 to v19	Update	Description added to HP Quick Release Bracket 2 in AMO

